



MITSUBISHI  
ELECTRIC

*Changes for the Better*

for a greener tomorrow

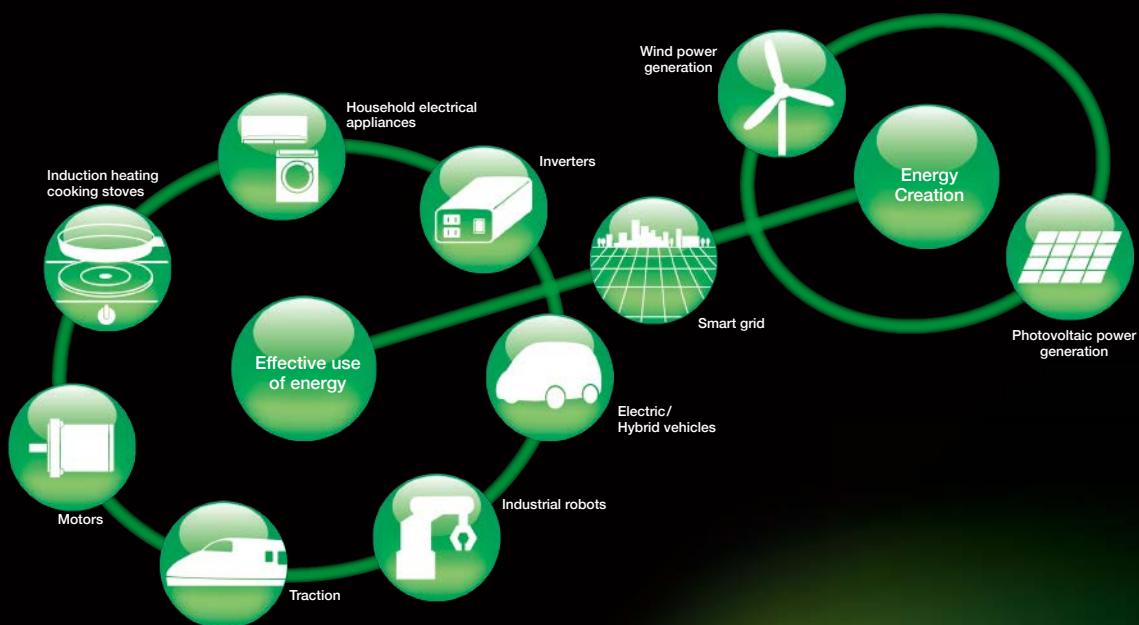


POWER MODULES

# Power Modules

# Innovative Power Devices for a Sustainable Future

Mitsubishi Electric power modules are at the forefront of the latest energy innovations that seek to solve global environmental issues while creating a more affluent and comfortable society for all. Some of these innovations are photovoltaic (PV) and wind power generation from renewable energy sources, smart grids realizing efficient supply of power, hybrid/electric vehicles (HVs/EVs) that take the next step in reducing carbon emissions and fuel consumption, and home appliances that achieve ground-breaking energy savings. Whether in appliances, railcars, EVs or industrial systems, our power modules are key elements in changing the way energy is used.





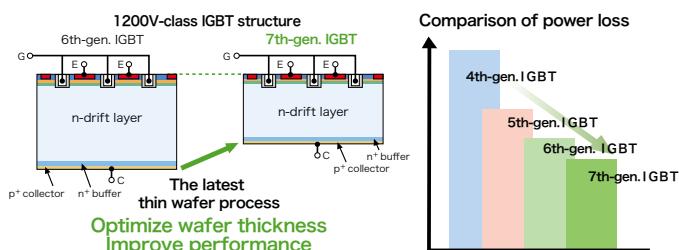
## Focus Technology

### 7th-Generation 1,200V-Class IGBT Chip Technology

Cutting-edge technology realizes energy-saving inverter devices

- Latest thin-wafer processing (n-drift layer) achieves thinner wafer than 6th-generation devices
- Performance improved by combining CSTBT™\* and light punch-through (LPT) structures
- Inverter system power dissipation minimized by its superior performance(lower V<sub>CEsat</sub> and E<sub>off</sub>)

\*CSTBT: Mitsubishi Electric's unique IGBT that makes use of carrier cumulative effect



#### A small surface mount package IPM has been newly developed for fan and low-power motor drive applications

##### Key Features

- Optimal pin layout realizes easier PCB wiring design and enables smaller PCB size
- Newly integrated interlock function in addition to conventional protection features for robust operation
- Bootstrap diode is integrated for the P-side drive power supply like conventional DIPIPM™ series, reducing the number of peripheral external parts

MISOP™  
Surface mount package IPM



#### Modules realizing single-control power supply and photocoupler-less systems for household appliances and low-capacity inverters

##### Key Features

- Transfer-molded structure incorporating a high thermal conductivity insulation sheet provides heat
- High-voltage IC equipped with drive, protection and level-shift circuits for direct control via input signals from a CPU or microcomputer
- Compact board and highly reliable equipment realized through single power-supply and photocoupler-less systems
- Includes built-in bootstrap diode (BSD)

DIPIPM™



#### Modules with built-in control and protection circuits for AC servo robots and PV power generation

##### Key Features

- Built-in protection circuits for short-circuiting, power supply undervoltage and overheating
- Highly compatible package with simplified printed circuit board (PCB) design
- Special intelligent power modules (IPMs) for power conditioners in PV power generation systems

IPM  
Intelligent Power Modules



#### IGBT modules for general-purpose inverters used in various applications

##### Key Features

- Various low-inductance packages and power chips available
- Compatible with high-frequency, high-voltage (1,700V) applications
- Large-capacity modules available for renewable energy systems

IGBT Modules  
Insulated Gate Bipolar Transistor Modules



#### High voltage, large capacity and high reliability are realized for traction and power transmission application

##### Key Features

- Two types of package are realized: "std type" with large output power and "LV100/HV100 type" for various inverter capacity by easy parallel connection
- The abundant field experience more than 20 years especially in the application of bullet train
- High reliability due to a long lifetime design and a robust design against severe environment

HVIGBT Modules  
High-Voltage Insulated Gate Bipolar Transistor Modules



#### Modules realizing high performance and reliability for propulsion inverters in HVs/EVs

##### Key Features

- Built-in temperature analog output function realizing highly reliable drive train
- High-power/temperature cycle life ensures high reliability
- Compliant with the End-of-life Vehicles Directive, regulations relating to substances of environmental concern
- High traceability in managing materials/components throughout the entire production process for each product

Power Modules for Vehicles  
Power Modules for EV/PHEV



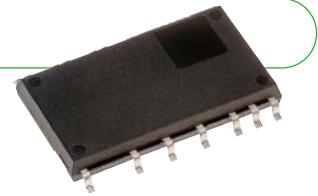
# Surface mount package IPM



## New Products

### Surface mount package IPM MISOP™

SP1SK, SP1SL, SP3SK and SP3SL



A small Surface mount package IPM has been newly developed for fan and low-power motor drive applications

#### <Main Features>

- Optimal pin layout realizes easier PCB wiring design and enables smaller PCB size
- Insulation distance between pins ensured, realizing easier board mounting without coating process
- Newly integrated interlock function in addition to conventional protection features for robust operation
- Installing RC-IGBT<sup>1</sup> simultaneously realizes compact package and low loss performance can go together
- Bootstrap diode is integrated for the P-side drive power supply like conventional DIPIPM™ series, reducing the number of peripheral external parts

\*1 Reverse-conducting IGBT

Type name	Rated current	Rated voltage	Chips	BSC	Protection	Shape
SP1SK**	1A	600V	RC-IGBT	-	UV	Surface mount package
SP1SL**			HVIC	Embedded	SC	
SP3SK**			LVIC	-	OT	
SP3SL**			BSD	Embedded	VOT IL	

[Term] VOT: Analog temperature output

★★:Under development

UV : Power supply under-voltage protection

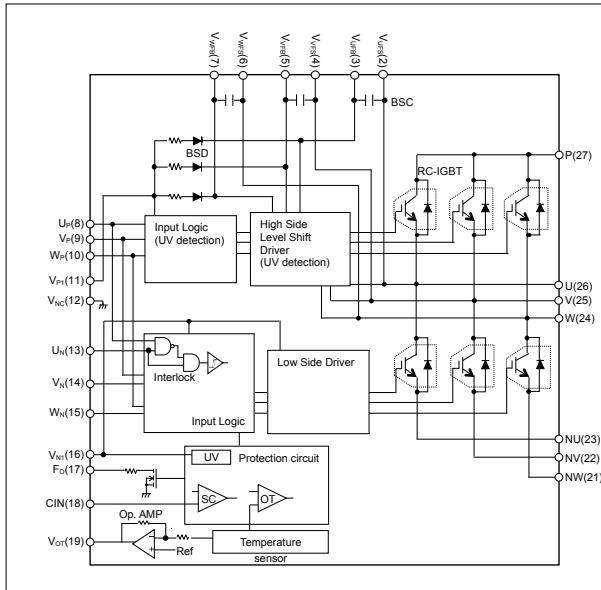
SC : Short-circuit protection

OT : Over Temperature protection

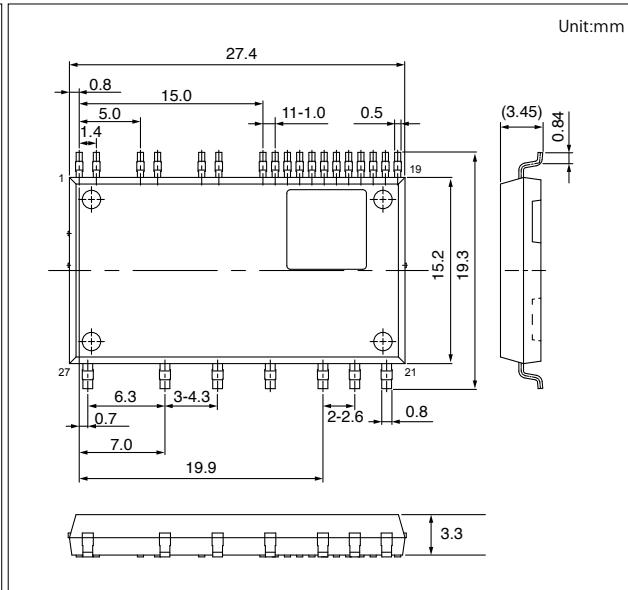
IL : Inter Lock

BSC : Bootstrap capacitor

### Schematic drawing



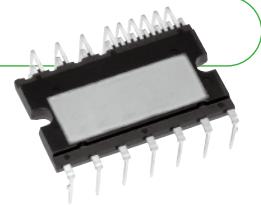
### Outline Drawing





## Feature Products

**Smaller package size realized by integrating newly designed RC-IGBT  
Recommended for low-cost inverter and fan controller applications**

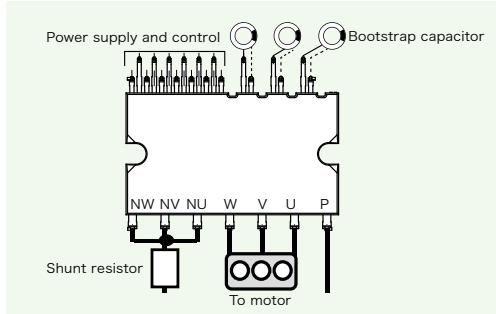


## SLIMDIP™

SLIMDIP-S, SLIMDIP-L

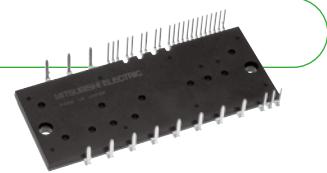
## &lt;Main Features&gt;

- RC-IGBT<sup>1</sup> incorporated, reducing package size 30% compared to Super-mini DIPIPM
- Maximum case temperature increased from 100°C to 115°C, increasing the operating temperature range and leading to easier system design
- Additional terminals for floating supply and built-in bootstrap diodes simplify PCB wiring pattern
- Both VOT<sup>2</sup> and OT<sup>3</sup> functions integrated for temperature protection

<sup>1</sup> RC-IGBT: Reverse conducting IGBT<sup>2</sup> VOT: Temperature information output function<sup>3</sup> OT: Over-temperature protection function

## Feature Products

**All-in-one intelligent power modules equipped with 3-phase converter and brake circuit in addition to inverter circuit**



## DIPIPM+™

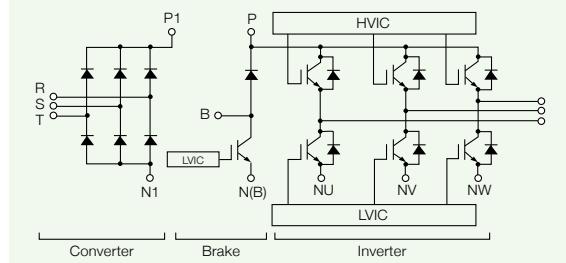
PSS05MC1FT, PSS10MC1FT, PSS15MC1FT,  
PSS25MC1FT, PSS35MC1FT, PSS50MC1F6

## &lt;Main Features&gt;

- Encapsulated with transfer molded resin, integrates three-phase converter, inverter, brake and control IC
- Built-in converter and brake enable system size to be reduced and save design cost, contributing to total cost reduction
- Lower PCB inductance pattern reduces noise, thereby reducing design time and countermeasure parts required for noise reduction
- Built-in BSD<sup>1</sup> with 1,200V withstand voltage reduces number of external parts and improves reliability

<sup>1</sup> BSD: Bootstrap diode<sup>2</sup>: Available without brake circuit

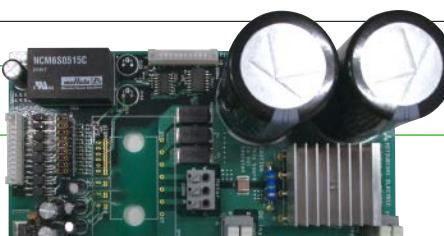
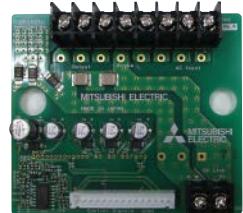
## Internal circuit diagram



## Customer Support

**EVA series, evaluation boards for each DIPIPM™**

**Various evaluation boards to easy support system design**

SLIMDIP™ evaluation board  
EVA01-SLIMSLIMDIP™ evaluation board  
EVA15-SLIMSuper mini DIPIPM™  
evaluation board  
EVA11-SDIPDIPIPM+™ evaluation board  
EVA14-DIP+DIPIPM+™  
evaluation  
board  
EVA03-DIP+

\* For further information, please contact sales office.

# Line-up of DIPIPM™

## ■ Series Matrix of 600V / 500V DIPIPM™

V <sub>CE(S)</sub> (V)		600V					500V	
I <sub>C</sub> (A)	Series	SLIMDIP	Super mini	Mini	Large	CIB/CI	Super mini	
			Ver.6		Ver.4	DIPIPM+	MOSFET	
3	SLIMDIP-S SLIMDIP-L							PSM03S93E5-A
5			PSS05S92F6-AG PSS05S92E6-AG	PSS05S51F6 PSS05S51F6-C				PSM05S93E5-A
10			PSS10S92F6-AG PSS10S92E6-AG	PSS10S51F6 PSS10S51F6-C				
15			PSS15S92F6-AG PSS15S92E6-AG	PSS15S51F6 PSS15S51F6-C			PSM15S94H6-A	
20			PSS20S92F6-AG PSS20S92E6-AG	PSS20S51F6 PSS20S51F6-C PSS20S71F6			PSM20S94H6-A	
30			PSS30S92F6-AG PSS30S92E6-AG	PSS30S71F6				
35			PSS35S92F6-AG PSS35S92E6-AG					
50				PSS50S71F6	PS21A79	PSS50MC1F6 PSS50NC1F6 *5		
75					PS21A7A			
Chip	IGBT/MOSFET	RC-IGBT	CSTBT	CSTBT	CSTBT	CSTBT	SJ-MOSFET	MOSFET
Protective Function	UV	P-side/N-side	P-side/N-side	P-side/N-side	P-side/N-side	P-side/N-side/Brake part	P-side/N-side	P-side/N-side
	SC	N-side	N-side	N-side	N-side with sense	N-side	N-side	N-side
	OT	N-side	N-side*1	—	—	—	—	N-side
	VOT	N-side	N-side*1	N-side	N-side	N-side	N-side	—
Specifications	Active input	High(3/5V)	High(3/5V)	High(3/5V)	High(3/5V)	High(5V)	High(3/5V)	High(3/5V)
	Emitter pin of N-side	Open	Open	Open	Open	Open	Open	Open
	Fault output	N-side(UV,SC,OT)	N-side (UV,SC,OT)	N-side (UV,SC)	N-side (UV,SC)	N-side (UV,SC)	N-side (UV,SC)	N-side (UV,SC,OT)
	Insulation voltage	2000Vrms*2	1500Vrms*2	2500Vrms	2500Vrms	2500Vrms	1500Vrms*2	1500Vrms*2
	Insulation structure	Insulation sheet	Insulation sheet	Molding resin*4/Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet	Insulation sheet
	RoHS directive	Compliant	Compliant	Compliant *3	Compliant	Compliant	Compliant	Compliant
	Pin type	Control side of zigzag (Long, Short)	Long	C: Control side of zigzag None: Short	—	—	Long	Long

[Notes] \*1 : PSSxxS92E6 has OT function, PSSxxS92F6 has V<sub>OT</sub> function

\*2 : AC60Hz,1minute.Corresponds to isolation voltage 2500Vrms  
in the case the convex-shaped heat sink

\*3 : High melting point solder (Lead Over 85%) is used  
for chip soldering of PSSxxS51F6 only.

\*4 : Molding resin insulation for PSSxxS51F6/C

\*5 : PSS50NC1F6 is not included brake.

[Term] CSTBT™: Mitsubishi Electric's unique IGBT that makes use of  
the carrier cumulative effect

RC-IGBT: Reverse conducting IGBT

HVIC: High Voltage IC, LVIC: Low Voltage IC,

BSD: Bootstrap Diode

UV: Supply Under Voltage protection,

OT: Over Temperature protection,

SC: Short Circuit protection

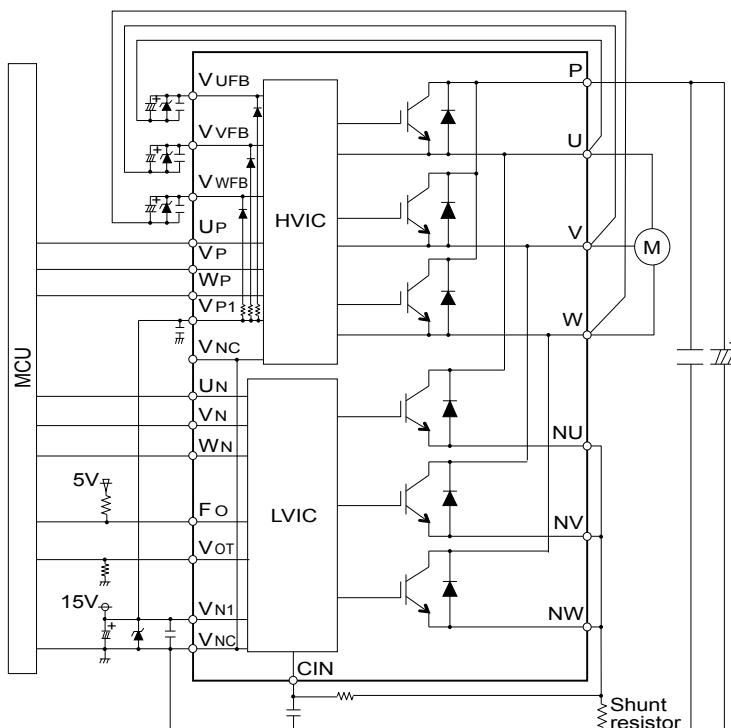
Vot: Analog temperature output

RoHS: Restriction of the use of certain Hazardous Substances  
in electrical and electronic equipment

CIB: Converter Inverter Brake,

CI: Converter Inverter

## ■ Application circuit of super mini DIPIPM™



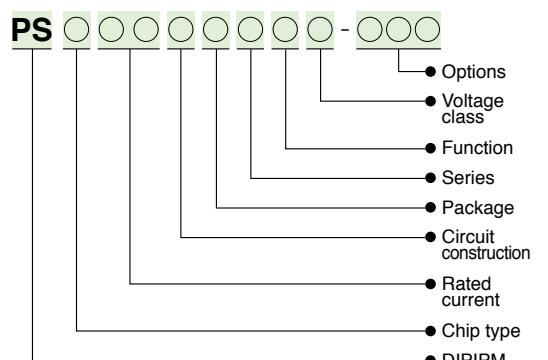
## ■ Series Matrix of 1200V DIPIPM™

V <sub>ces</sub> (V)		1200V		
I <sub>c</sub> (A)	Series	Mini	Large	
			Ver.6	Ver.4
5	PSS05S72FT	PSS05SA2FT	PS22A72	PSS05MC1FT PSS05NC1FT*1
10	PSS10S72FT	PSS10SA2FT	PS22A73	PSS10MC1FT PSS10NC1FT*1
15		PSS15SA2FT	PS22A74	PSS15MC1FT PSS15NC1FT*1
25		PSS25SA2FT	PS22A76	PSS25MC1FT PSS25NC1FT*1
35		PSS35SA2FT	PS22A78-E	PSS35MC1FT PSS35NC1FT*1
50		PSS50SA2FT	PS22A79	
75		PSS75SA2FT*		
Chip	IGBT/MOSFET	CSTBT	CSTBT	CSTBT
Protective Function	UV	P-side/N-side	P-side/N-side	P-side/N-side/Brake
	SC	N-side	N-side	N-side
	OT	—	—	—
	V <sub>OT</sub>	N-side	N-side	N-side
Specifications	Active input	High(5V)	High(5V)	High(5V)
	Emitter pin of N-side	Open	Open	Open
	Fault output	N-side (UV,SC)	N-side (UV,SC)	N-side (UV,SC)
	Insulation voltage	2500Vrms	2500Vrms	2500Vrms
	Insulation structure	Insulation sheet	Insulation sheet	Insulation sheet
	RoHS directive	Compliant	Compliant	Compliant
	Pin type	—	—	—

★: New Product    Non-recommended : Please contact to the sales offices.

[Notes] \*1: PSS\*\*NC1FT is not included brake

## ■ Type Name Definition of DIPIPM™



[Term]
 

- BSD: Bootstrap Diode
- CSTBT™: Mitsubishi Electric's unique IGBT that makes use of the carrier cumulative effect.
- HVIC: High Voltage IC, LVIC: Low Voltage IC
- UV: Supply Under Voltage protection, OT: Over Temperature protection, SC: Short Circuit protection
- VOT: Analog temperature output
- RoHS: Restriction of hazardous substances in electrical and electronic equipment
- CIB: Converter Inverter Brake, CI: Converter Inverter

# Line-up of DIPIPM™

## Outline Drawing of DIPIPM™

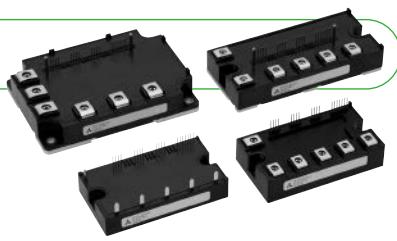
Unit:mm

<p><b>Super mini DIPIPM Ver.6 MOSFET Super mini DIPIPM Long (A)</b></p> <p>This diagram shows the physical dimensions of the Super mini DIPIPM Ver.6 MOSFET Super mini DIPIPM Long (A) package. Key dimensions include a total width of 38.05 mm, a height of 12 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	<p><b>Mini DIPIPM (PSSxxS71F6) 1200V Mini DIPIPM</b></p> <p>This diagram shows the physical dimensions of the Mini DIPIPM (PSSxxS71F6) 1200V Mini DIPIPM package. Key dimensions include a total width of 46.228 mm (26x1.778 mm), a height of 15.5 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	<p><b>Mini DIPIPM (PSSxxS51F6)</b></p> <p>This diagram shows the physical dimensions of the Mini DIPIPM (PSSxxS51F6) package. Key dimensions include a total width of 46.228 mm (26x1.778 mm), a height of 15.25 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>
<p><b>Mini DIPIPM(PSSxxS51F6-C) Zigzag(C)</b></p> <p>This diagram shows the physical dimensions of the Mini DIPIPM (PSSxxS51F6-C) Zigzag(C) package. Key dimensions include a total width of 46.228 mm (26x1.778 mm), a height of 15.25 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	<p><b>Large DIPIPM</b></p> <p>This diagram shows the physical dimensions of the Large DIPIPM package. Key dimensions include a total width of 46.228 mm (26x1.778 mm), a height of 15.25 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	<p><b>DIPIPM+</b></p> <p>This diagram shows the physical dimensions of the DIPIPM+ package. Key dimensions include a total width of 46.228 mm (26x1.778 mm), a height of 15.25 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>
<p><b>SLIMDIP Long</b></p> <p>This diagram shows the physical dimensions of the SLIMDIP Long package. Key dimensions include a total width of 32.8 mm, a height of 18.8 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	<p><b>SLIMDIP Short</b></p> <p>This diagram shows the physical dimensions of the SLIMDIP Short package. Key dimensions include a total width of 32.8 mm, a height of 18.8 mm, and a thickness of 0.5 mm. The package features a heat sink side with a width of 14x2.54 mm (35.56 mm total) and a height of 10.5 mm. Lead spacing is 0.5 mm, and lead height is 0.5 mm. A 'Type name, Lot No.' marking area is located on the top surface.</p>	



## New Products

**Loaded with built-in functions, contributing to inverters with enhanced energy savings**



### G1 Series IPM with 7th-generation IGBT

#### <Main Features>

- Power loss has been reduced with the introduction of the 7th-generation IGBT produced using CSTBT™<sup>1</sup> and a diode incorporating a RFC<sup>2</sup> structure that contributes to reducing the power consumed in inverters
- The new resin-insulated metal baseplate, originally introduced in 7th-generation IGBT modules, eliminates the solder-attached section, increasing the thermal cycle lifetime and improving inverter reliability
- In addition to the built-in functions of the previous product,<sup>3</sup> automatic switching speed control, error detection function and Bootstrap diode (BSD)<sup>4</sup> contribute to lowering inverter loss and shortening design time
- The introduction of PC-TIM<sup>5</sup> contribute to simplifying the inverter assembly process (optional)

\*1 CSTBT™: Mitsubishi Electric's unique IGBT that utilizes the carrier cumulative effect

\*2 RFC: Relaxed field cathode

\*3 Conventional product: IPM L1-Series

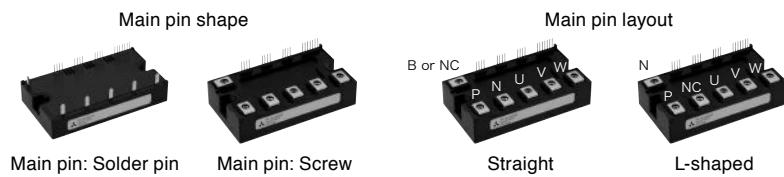
Built-in functions: Supply Undervoltage lock protection (UV), Short-circuit protection (SC), Over-temperature protection (OT)

\*4 Bootstrap diode (BSD): Optional products include 50A, 75A, 100A/650V, 25A, 35A, 50A /1200V

\*5 PC-TIM: Phase change-thermal interface material

#### ■ "A" package main pin shape and layout

For the "A" package 6-in-1 (CG1A) main pin shape, select either solder pin or screw type  
For the pin layout, select either straight or L-shaped



#### ■ Lineup

V <sub>CES</sub> (V)	Package	Main pin shape	Main pin layout	I <sub>c</sub> (A)									
				25	35	50	75	100	150	200	300	450	
650V	A package	Screw	Straight			PM50CG1A065*	PM75CG1A065*	PM100CG1A065*					
			L-shaped			PM50CG1AL065*	PM75CG1AL065*	PM100CG1AL065*					
		Solder pin	Straight			PM50CG1AP065*	PM75CG1AP065*	PM100CG1AP065*					
			L-shaped			PM50CG1APL065*	PM75CG1APL065*	PM100CG1APL065*					
	B package	Screw	L-shaped			PM50CG1B065*	PM75CG1B065*	PM100CG1B065*	PM150CG1B065*	PM200CG1B065*			
	C package	Screw	L-shaped							PM200CG1C065*	PM300CG1C065*	PM450CG1C065*	
1200V	A package	Screw	Straight	PM25CG1A120*	PM35CG1A120*	PM50CG1A120*							
			L-shaped	PM25CG1AL120*	PM35CG1AL120*	PM50CG1AL120*							
		Solder pin	Straight	PM25CG1AP120*	PM35CG1AP120*	PM50CG1AP120*							
			L-shaped	PM25CG1APL120*	PM35CG1APL120*	PM50CG1APL120*							
	B package	Screw	L-shaped	PM25CG1B120*	PM35CG1B120*	PM50CG1B120*	PM75CG1B120*	PM100CG1B120*					
	C package	Screw	L-shaped					PM100CG1C120*	PM150CG1C120*	PM200CG1C120*			

★: New Product

Representative reference is "A" package with screw terminal and straight layout (CG1A).

# Line-up of IPM

Matrix of IPM Modules 650V/600V (No.: Number of outline drawing, see page 11 to 12)

V <sub>CES(V)</sub> Series I <sub>C(A)</sub>	650V			600V			Photovoltaic			L Series		
	G1 Series		L1 Series	S1 Series		V1 Series	Photovoltaic		L Series			
	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.
50	PM50CG1A065*	C 12					PM50B4LA060	B4 01				
	PM50RG1A065*	R 12	PM50CL1A060	C 01			PM50B5LA060	B5 01				
	PM50CG1B065*	C 10	PM50CL1B060	C 02			PM50B6LA060	B6 01	PM50CLA060	C		
	PM50RG1B065*	R 10	PM50RL1A060	R 01	PM50CS1D060	C 05	PM50B4LB060	B4 02	PM50CLB060	C		
	PM50CG1AL065*	C 12	PM50RL1B060	R 02			PM50B5LB060	B5 02	PM50RLA060	R		
	PM50CG1AP065*	C 09	PM50RL1C060	R 03			PM50B6LB060	B6 02	PM50RLB060	R		
	PM50CG1APL065*	C 09					PM50B4L1C060	B4 03				
	PM50RG1AP065*	R 09					PM50B5L1C060	B5 03				
	PM50RG1APL065*	R 09					PM50B6L1C060	B6 03				
75	PM75CG1A065*	C 12					PM75B4LA060	B4 01				
	PM75RG1A065*	R 12	PM75CL1A060	C 01			PM75B5LA060	B5 01				
	PM75CG1B065*	C 10	PM75CL1B060	C 02			PM75B6LA060	B6 01	PM75CLA060	C		
	PM75RG1B065*	R 10	PM75RL1A060	R 01	PM75CS1D060	C 05	PM75B4LB060	B4 02	PM75CLB060	C		
	PM75CG1AL065*	C 12	PM75RL1B060	R 02			PM75B5LB060	B5 02	PM75RLA060	R		
	PM75CG1AP065*	C 09	PM75RL1C060	R 02			PM75B6LB060	B6 02	PM75RLB060	R		
	PM75CG1APL065*	C 09					PM75B4L1C060	B4 03				
	PM75RG1AP065*	R 09					PM75B5L1C060	B5 03				
	PM75RG1APL065*	R 09					PM75B6L1C060	B6 03				
100	PM100CG1A065*	C 12										
	PM100CG1B065*	C 10	PM100CL1A060	C 01								
	PM100RG1B065*	R 10	PM100CL1B060	C 02								
	PM100CG1AL065*	C 12	PM100RL1A060	R 01	PM100CS1D060	C 05						
	PM100CG1AP065*	C 09	PM100RL1B060	R 02								
	PM100CG1APL065*	C 09										
150	PM150CG1B065*	C 10	PM150CL1A060	C 01								
	PM150RG1B065*	R 10	PM150CL1B060	C 02								
	PM150RL1A060	R 01	PM150CS1D060	C 05								
	PM150RL1B060	R 02										
200	PM200CG1B065*	C 10										
	PM200RG1B065*	R 10	PM200CL1A060	C 04								
	PM200CG1C065*	C 11	PM200RL1A060	R 04	PM200CS1D060	C 05						
	PM200RG1C065*	R 11										
300	PM300CG1C065*	C 11	PM300CL1A060	C 04								
	PM300RG1C065*	R 11	PM300RL1A060	R 04								
400/450	PM450CG1C065*	C 11					PM400DV1A060	D 06				
	PM450RG1C065*	R 11										
600							PM600DV1A060	D 06				
800							PM800DV1B060	D 07				
IGBT chip	CSTBT*1 Emitter sensor installed Temperature sensor installed		CSTBT*1 Built-in emitter sensor Built-in temperature sensor		CSTBT*1 Built-in emitter sensor Built-in temperature sensor		CSTBT*1 Built-in emitter sensor Built-in temperature sensor		CSTBT*1 Built-in emitter sensor Built-in temperature sensor		CSTBT*2 Built-in emitter sensor Built-in temperature sensor	
UV	P-side/N-side		P-side/N-side		N-side		P-side/N-side		P-side/N-side		P-side/N-side	
OT	P-side/N-side		P-side/N-side		N-side		P-side/N-side		P-side/N-side		P-side/N-side	
SC	P-side/N-side		P-side/N-side		N-side		P-side/N-side		P-side/N-side		P-side/N-side	
Identification	P-side/N-side		—		—		—		—		—	
RoHS directive	Compliant		Compliant		Compliant		Compliant		Compliant		Compliant	
Compatibility	—		L Series		S-DASH SERVO		V Series		—		—	
Connection	D	B4	B5	B6	C	R						

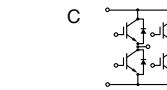
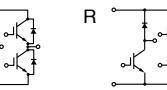
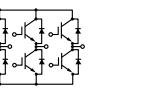
★: New Product

Non-recommended : Please contact to the sales offices.

[Notes] \*1: Full-gate CSTBT™ \*2: PCM (Plugged Cell Merged) CSTBT™

[Term] UV: Supply Under Voltage-lock protection, SC: Short-Circuit protection, OT: Over-temperature protection,  
OC: Over-current protection, CSTBT™: Mitsubishi Electric's unique IGBT that makes use of the carrier cumulative effect  
RoHS: Restriction of hazardous substances in electrical and electronic equipment

## Matrix of IPM Modules 1200V (No.: Number of outline drawing, see page 11 to 12)

V <sub>ces(V)</sub> Series I <sub>c(A)</sub>	1200V													
	G1 Series			L1 Series			S1 Series			V1 Series			L Series	
	Connection	No.		Connection	No.		Connection	No.		Connection	No.		Connection	No.
25	PM25CG1A120*	C 12		PM25CL1A120	C 01		PM25CS1D120	C 05				PM25CLA120	C	
	PM25CG1B120*	C 10		PM25CL1B120	C 02							PM25CLB120	C	
	PM25RG1A120*	R 12		PM25RL1A120	R 01							PM25RLA120	R	
	PM25RG1B120*	R 10		PM25RL1B120	R 02							PM25RLB120	R	
	PM25CG1AL120*	C 12		PM25RL1C120	R 03									
	PM25CG1AP120*	C 09												
	PM25CG1APL120*	C 09												
	PM25RG1AP120*	R 09												
35	PM35CG1A120*	C 12												
	PM35CG1B120*	C 10												
	PM35RG1A120*	R 12												
	PM35RG1B120*	R 10												
	PM35CG1AL120*	C 12												
	PM35CG1AP120*	C 09												
	PM35CG1APL120*	C 09												
	PM35RG1AP120*	R 09												
50	PM50CG1A120*	C 12		PM50CL1A120	C 01		PM50CS1D120	C 05				PM50CLA120	C	
	PM50CG1B120*	C 10		PM50CL1B120	C 02							PM50CLB120	C	
	PM50RG1B120*	R 10		PM50RL1A120	R 01							PM50RLA120	R	
	PM50CG1AL120*	C 12		PM50RL1B120	R 02							PM50RLB120	R	
	PM50CG1AP120*	C 09												
	PM50CG1APL120*	C 09												
75	PM75CG1B120*	C 10		PM75CL1A120	C 01		PM75CS1D120	C 05				PM75CLA120	C	
	PM75RG1B120*	R 10		PM75CL1B120	C 02							PM75CLB120	C	
	PM75RL1A120	R 01										PM75RLA120	R	
	PM75RL1B120	R 02										PM75RLB120	R	
100	PM100CG1B120*	C 10		PM100CL1A120	C 04		PM100CS1D120	C 05				PM100CLA120	C	
	PM100CG1C120*	C 11		PM100CL1B120	R 04							PM100CLB120	R	
	PM100RG1B120*	R 10		PM100RL1A120										
	PM100RG1C120*	R 11												
150	PM150CG1C120*	C 11		PM150CL1A120	C 04							PM150CLA120	C	
	PM150RG1C120*	R 11		PM150RL1A120	R 04							PM150RLA120	R	
200	PM200CG1C120*	C 11								PM200DV1A120	D 06	PM200CLA120	C 08	
	PM200RG1C120*	R 11												
300										PM300DV1A120	D 06	PM300CLA120	C 08	
450										PM450DV1A120	D 06	PM450CLA120	C 08	
IGBT chip	CSTBT* <sup>1</sup> Emitter sensor installed Temperature sensor installed			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>2</sup> Built-in current sensor Built-in temperature sensor	
	CSTBT* <sup>1</sup> Temperature sensor installed			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>1</sup> Built-in current sensor Built-in temperature sensor			CSTBT* <sup>2</sup> Built-in current sensor Built-in temperature sensor	
Fault output	UV	P-side/N-side			P-side/N-side			N-side			P-side/N-side			P-side/N-side
	OT	P-side/N-side			P-side/N-side			N-side			P-side/N-side			P-side/N-side
	SC	P-side/N-side			P-side/N-side			N-side			P-side/N-side			P-side/N-side
Identification		P-side/N-side			—			—			—			—
		Compliant			Compliant			Compliant			Compliant			Compliant
Compatibility		—			L Series			S-DASH SERVO			V Series			—
Connection	D				C				R					

★: New Product    Non-recommended : Please contact to the sales offices.

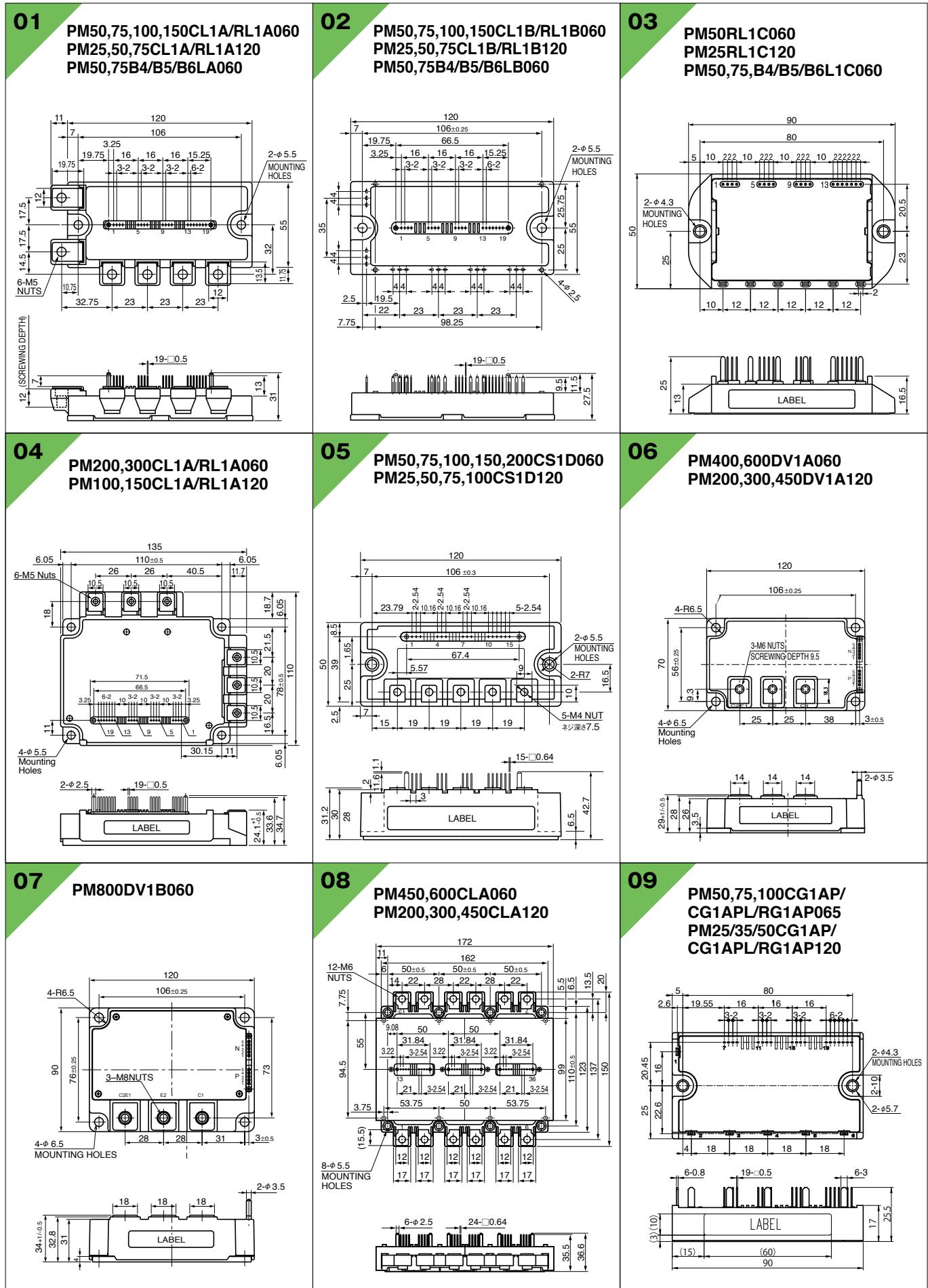
[Notes] \*1: Full-gate CSTBT™ \*2: PCM (Plugged Cell Merged) CSTBT™

[Term] UV : Supply Under Voltage-lock protection, SC : Short-Circuit Protection, OT : Over-temperature protection,  
OC : Over-current protection, RoHS : the Restriction of the use of certain Hazardous Substances in electrical and electronic equipment

# Line-up of IPM

## ■ Outline Drawing of IPM

Unit:mm

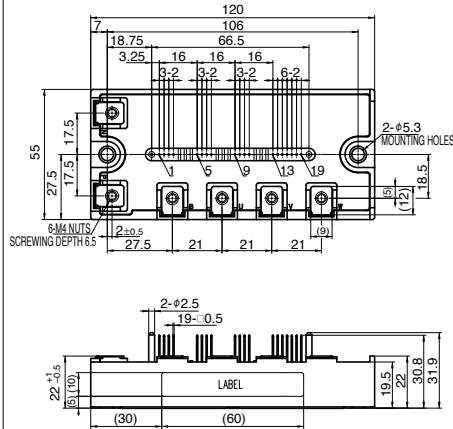


## ■ Outline Drawing of IPM

Unit:mm

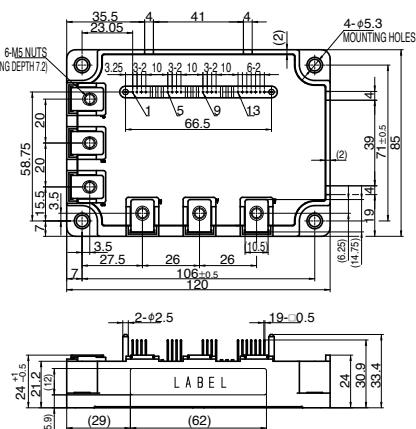
10

**PM50,75,100,150,200CG1B/  
RG1B065  
PM25,35,50,75,100CG1B/  
RG1B120**



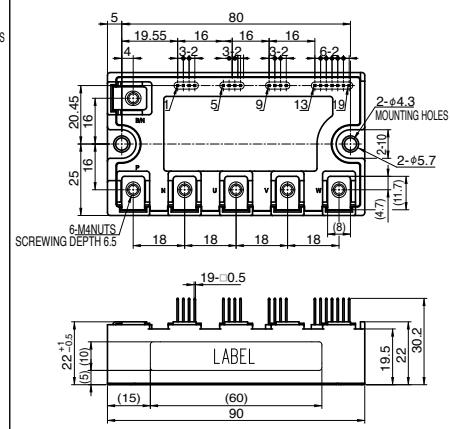
11

**PM200,300,400,450CG1C/  
RG1C065  
PM100,150,200CG1C/  
RG1C120**



12

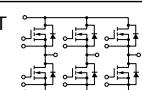
**PM50,75,100CG1A/CG1AL/  
RG1A065  
PM25/35/50CG1A/CG1AL/  
RG1A120**



# Line-up of MOSFET Modules

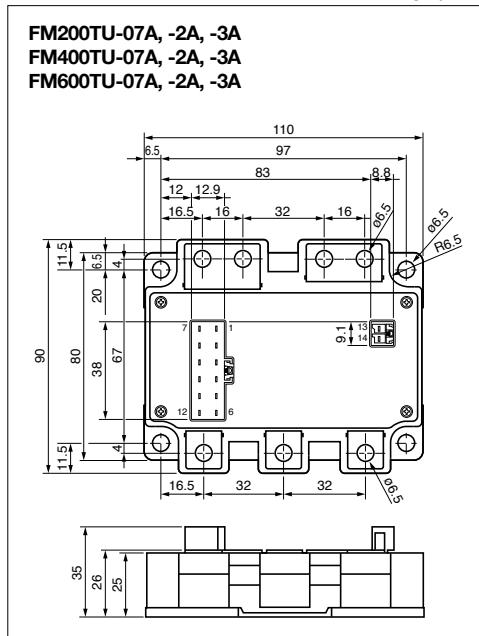
## ■ Series Matrix of MOSFET Modules

RoHS directive compliant

$V_{DSS}$ $I_D$ (A)	75V	Connection	100V	Connection	150V	Connection
100	FM200TU-07A	T	FM200TU-2A	T	FM200TU-3A	T
200	FM400TU-07A	T	FM400TU-2A	T	FM400TU-3A	T
300	FM600TU-07A	T	FM600TU-2A	T	FM600TU-3A	T
Connection						

## ■ Outline Drawing of MOSFET Modules

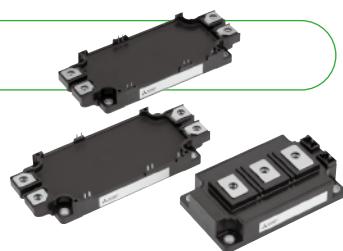
Unit:mm





## New Products

New lineup contributes to simplifying design, downsizing, energy-saving s of industrial inverters.



### IGBT Module T/T1-Series

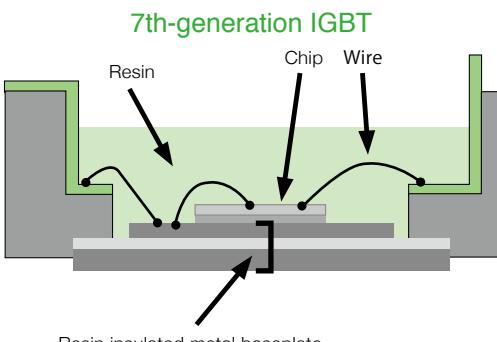
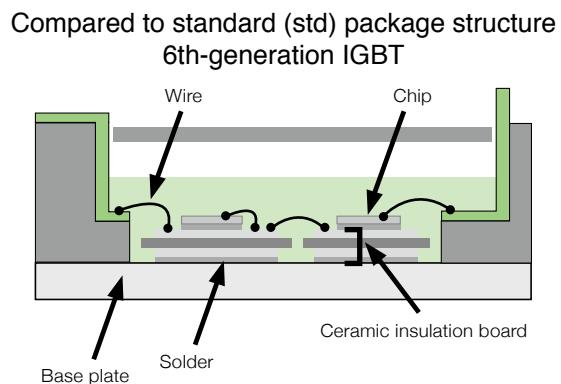
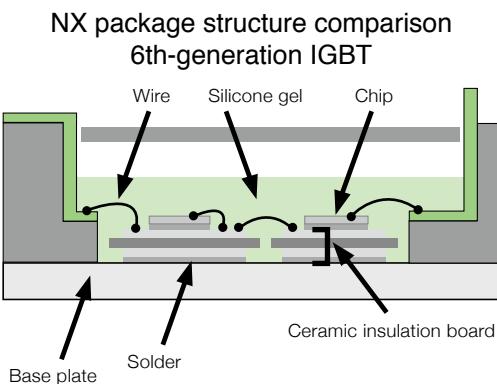
#### <Main Features>

- New modules equipped with three-phase converter, inverter, and brake circuit(CIB), contributes to simplifying design for inverter systems
- CIB modules contribute to compact inverter systems by reducing package size by 36% compared to the Mitsubishi Electric's existing module.(CIB)
- Power loss has been reduced with the introduction of the 7th-generation IGBT produced using CSTBT™<sup>2</sup> and a diode incorporating a relaxed field of cathode (RFC) structure
- The new structure introduced eliminates the solder-attached section, increasing the thermal cycle lifetime, which contributes to improving the reliability of inverters
- The introduction of press-fit pins and PC-TIM<sup>1</sup> contribute to simplifying the assembly process for inverters

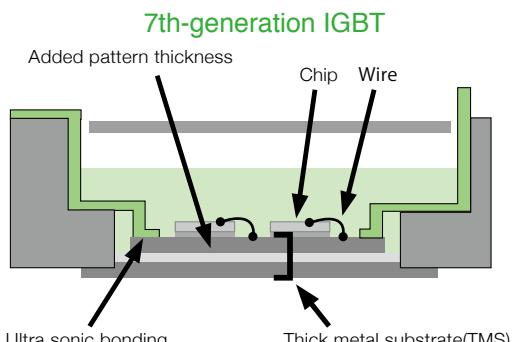
\*1 PC-TIM: Phase change - thermal interface material

\*2 CSTBT™: Mitsubishi Electric's unique IGBT that makes use of the carrier cumulative effect

#### ■ New structure realizes improved reliability (improved thermal cycle lifetime)



※Adopts SoLid Cover(SLC) Technology



※Standard package is not available for CIB

#### ◆ Press-fit terminal support (NX)

- Possible to select the control pin shape (soldered terminals/press-fit terminals)
- Solder attachment process eliminated

#### ■ Press-fit pin



① Main pin



② Signal pin



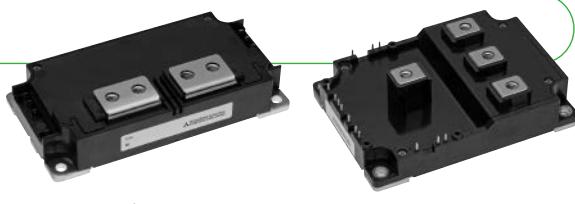
## Feature Products

Contributes to realizing smaller, energy-saving large-capacity inverters

### Power Modules for 3-level Inverters

#### <Main Features>

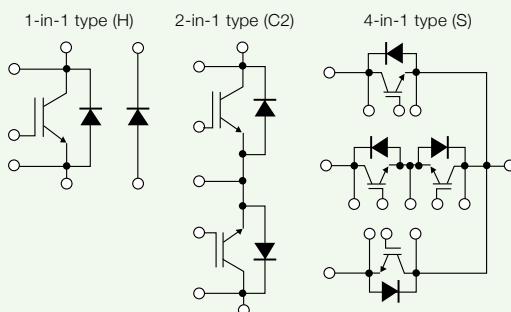
- Compatible with 3-level inverters, reducing power consumption approx. 30%<sup>\*1</sup>
- New package developed<sup>\*2</sup> contributing to lower inductance and simplified inverter circuit structure
- IGBT specifications optimized<sup>\*3</sup> with development of new compact, low-inductance package
- 4-in-1<sup>\*4</sup> and 1-in-1/2-in-1<sup>\*5</sup> lineup contributes to improved compactness and freedom in inverter design



1-in-1 / 2-in-1 type

4-in-1 type

### Internal circuit diagram



<sup>\*1</sup> Comparison between 3-level inverter incorporated in this device and 2-level inverter in conventional device.

<sup>\*2</sup> 2 1-in-1/2-in-1 type external dimensions of 130x67mm, 4-in-1 type external dimensions of 115x82mm, new package developed with innovative terminal positioning.

<sup>\*3</sup> IGBT specifications optimized for 3-level inverters, adopting CSTBT™ (Mitsubishi Electric's unique IGBT that makes use of the carrier cumulative effect).

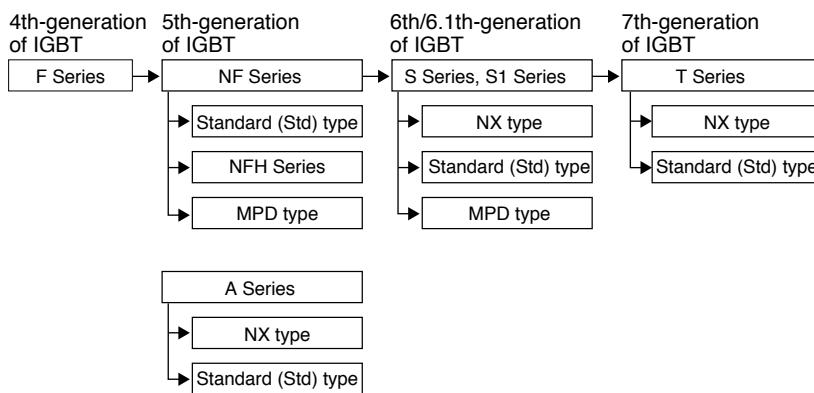
<sup>\*4</sup> 4-in-1 module with one 3-level inverter arm in one package.

<sup>\*5</sup> Bidirectional switch model as emitter common connection.

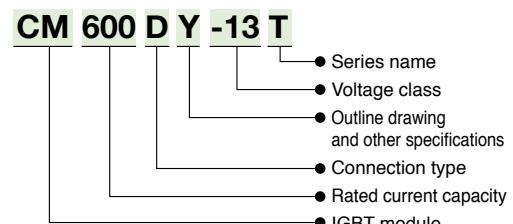
### Lineup

Main application	Model	Module type	Rated voltage	Rated current	Circuit structure	External dimensions WxD (mm)
125-500kW inverter	CM400ST-24S1	IGBT	1200V	400A	4-in-1	115x82
500kW - inverter	CM1400HA-24S	IGBT	1200V	1400A	1-in-1	130x67
	RM1400HA-24S	Diode	1200V	1400A	1-in-1	130x67
	CM1000HA-34S	IGBT	1700V	1000A	1-in-1	130x67
	CM500C2Y-24S	IGBT	1200V	500A	2-in-1	130x67

### Evolution of IGBT Module Series



### Type Name Definition of IGBT Modules



### Features of IGBT Module Series

#### S Series

- Lineup includes various package types
- 6th-generation CSTBT™ delivers low-loss performance
- Thinner package (Height: 17mm) (NX type)
- Suited to large-capacity applications (MPD type)

MPD: Mega power dual

#### NFH Series

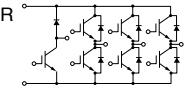
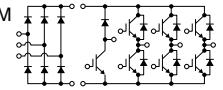
- High-speed CSTBT™ delivers low-loss performance
- Soft switching (resonant) turn-off function (ZVS)
- Enhanced inner wiring (skin effect)

CSTBT™: Mitsubishi Electric's unique IGBT that makes use of the carrier cumulative effect.

# Line-up of IGBT Modules

## Matrix of IGBT Modules 650V/600V (No.: Number of outline drawing, see page 19 to 20)

RoHS directive (2011/65/EU) compliant

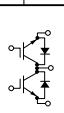
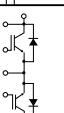
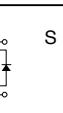
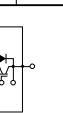
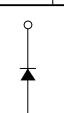
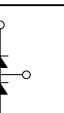
V <sub>CES</sub> (V)	650V						600V						RoHS directive (2011/65/EU) compliant			
	Series Ic(A)	T/T1-Series NX Type	Connection	No.	T-Series std Type	Connection	No.	A-Series NX Type	Connection	No.	NF-Series	Connection	No.	NF-Series NFH Type	Connection	No.
50	CM50MXUB-13T★★ CM50MXUB-13T1★★ CM50MXUBP-13T★★ CM50MXUBP-13T1★★	M M M M	42 42 - -													
75	CM75MXUB-13T★★ CM75MXUB-13T1★★ CM75MXUBP-13T★★ CM75MXUBP-13T1★★	M M M M	42 42 - -					CM75MX-12A	M 01	CM75TL-12NF CM75RL-12NF	T R	07 07				
100	CM100TX-13T★ CM100TP-13T★ CM100MXUB-13T★★ CM100MXUB-13T1★★ CM100MXUBP-13T★★ CM100MXUBP-13T1★★ CM100MXUD-13T★★ CM100MXUD-13T1★★ CM100MXUDP-13T★★ CM100MXUDP-13T1★★	T T M M M M M M M M	33 37 42 42 - - 44 44 - -	CM100DY-13T★	D 30	CM100MX-12A CM100RX-12A	M R 01 02	CM100TL-12NF CM100RL-12NF	T R	07 07	CM100DUS-12F	D	13			
150	CM150TX-13T★ CM150TP-13T★ CM150RX-13T★ CM150RXP-13T★ CM150MXUD-13T★★ CM150MXUD-13T1★★ CM150MXUDP-13T★★ CM150MXUDP-13T1★★	T T R R M M M M	33 37 34 38 44 44 - -	CM150DY-13T★	D 30	CM150RX-12A	R 02	CM150DY-12NF CM150TL-12NF CM150RL-12NF	D T R	08 07 07	CM150DUS-12F	D	13			
200	CM200TX-13T★ CM200TP-13T★ CM200RX-13T★ CM200RXP-13T★	T T R R	33 37 34 38	CM200DY-13T★	D 30	CM200RX-12A	R 02	CM200DY-12NF CM200TL-12NF CM200RL-12NF	D T R	08 09 09	CM200DU-12NFH	D	13			
225																
300	CM300DX-13T★ CM300DXP-13T★	D D	28 39	CM300DY-13T★	D 31	CM300DX-12A	D 03	CM300DY-12NF	D 08	CM300DU-12NFH	D	14				
400					CM400DY-13T★	D 31	CM400DX-12A	D 03	CM400DY-12NF	D 10	CM400DU-12NFH	D	14			
450	CM450DX-13T★ CM450DXP-13T★	D D	28 39													
600	CM600DX-13T★ CM600DXP-13T★	D D	28 39	CM600DY-13T★	D 32			CM600DY-12NF	D 11	CM600DU-12NFH	D	15				
1000																
Connection	D 	T 	R 	M 												

★★: Under Development ★: New Product

Non-recommended : Please contact to the sales offices.

## Matrix of Power Modules for 3-level Inverter (No.: Number of outline drawing, see page 22 to 23)

RoHS directive (2011/65/EU) compliant

V <sub>CES</sub> /V <sub>RRM</sub>	1200 V IGBT Module			1700 V IGBT Module			1200 V Diode Module			1700 V Diode Module			
	Ic/I <sub>F</sub>	T/S/S1-Series std Type	Connection	No.	S/S1-Series std Type	Connection	No.	S/S1-Series std Type	Connection	No.	S/S1-Series std Type	Connection	No.
400	CM400ST-24S1★ CM400C1Y-24S	S C1	35 11										
450	CM450C1Y-24T★★	C1	32										
500	CM500C2Y-24S★	C2	36										
600	CM600C1Y-24T★	C1	32	CM600HA-34S★	H	36					RM600DY-34S★	D	32
800				CM800HA-34S★	H	36					RM800DY-34S★	D	32
1000				CM1000HA-34S★	H	36							
1400	CM1400HA-24S★	H	36				RM1400HA-24S★	H	36				
Connection	IGBT module	C1 	C2 	H 	S 		Diode module	H 	D 				

\* Connection of diode module and IGBT module are different.

★★: Under Development ★: New Product

# Line-up of IGBT Modules

## Matrix of IGBT Modules 1200V (No.: Number of Outline Drawing, see page 19 to 23)

RoHS directive (2011/65/EU) compliant

VCES(V)		1200V														
Series Ic	T/T1-Series NX Type	T-Series std Type			S/S1-Series NX Type			S/S1-Series std Type			S/S1-Series MPD Type			A-Series <sup>※1</sup> NF-Series <sup>※1</sup>		
		Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	Connection	No.	
35	CM35MXUA-24T** CM35MXUA-24T1** CM35MXUAP-24T** CM35MXUAP-24T1**	M M M M	41 41 -			CM35MXA-24S	M M	04 04								
50	CM50MXUA-24T** CM50MXUA-24T1** CM50MXUAP-24T** CM50MXUAP-24T1**	M M M M	41 41 -			CM50MXA-24S	M M	04 04						CM50RL-24NF CM50TL-24NF	R T 07 07	
75	CM75MXUB-24T** CM75MXUB-24T1** CM75MXUBP-24T** CM75MXUBP-24T1** CM75MXUC-24T** CM75MXUC-24T1** CM75MXUCP-24T** CM75MXUCP-24T1**	M M M M M M M M	42 42 -			CM75MXA-24S CM75TX-24S CM75RX-24S	M T R	04 05 02						CM75RL-24NF CM75TL24NF	R T 07 07	
100	CM100TX-24T* CM100TXP-24T* CM100RX-24T* CM100RXP-24T* CM100MXUC-24T** CM100MXUC-24T1** CM100MXUCP-24T** CM100MXUCP-24T1**	T T R R M M M M	33 37 34 38 43 43 -	CM100DY-24T*	D 30	CM100MXA-24S CM100TX-24S1 CM100RX-24S1	M T R	04 25 26						CM100DY-24A CM100DY-24NF CM100E3Y-24NF CM100RL-24NF CM100TL-24NF CM100DU-24NFH	D D E3 R T D 08 08 08 07 07 13	
150	CM150TX-24T* CM150TXP-24T* CM150RX-24T* CM150RXP-24T* CM150MXUD-24T** CM150MXUD-24T1** CM150MXUDP-24T** CM150MXUDP-24T1**	T T R R M M M M	33 37 34 38 44 44 -	CM150DY-24T*	D 30	CM150DX-24S CM150EXS-24S CM150TX-24S1 CM150RX-24S1	D E T R	03 24 25 26						CM150DY-24A CM150DY-24NF CM150E3Y-24NF CM150RL-24NF CM150TL-24NF CM150DU-24NFH	D D E3 R T D 08 08 08 09 09 13	
200	CM200TX-24T* CM200TXP-24T*	T T	33 37	CM200DY-24T*	D 31	CM200EXS-24S CM200RXL-24S	E R	24 21						CM200DY-24A CM200DY-24NF CM200RL-24NF CM200TL-24NF CM200DU-24NFH	D D R T D 08 10 09 09 14	
225	CM225DX-24T* CM225DXP-24T*	D D	28 39			CM225DX-24S1	D	27								
300	CM300DX-24T* CM300DXP-24T*	D D	28 39	CM300DY-24T*	D 31	CM300DX-24S1 CM300EXS-24S CM300RXL-24S1*	D E R	27 24 21	CM300DY-24S	D 10				CM300DY-24A CM300DY-24NF CM300DU-24NFH	D D D 10 11 14	
400															CM400DY-24A CM400HA-24A CM400DY-24NF CM400DU-24NFH	D H D D 11 16 11 15
450	CM450DX-24T* CM450DXP-24T*	D D	28 39	CM450DY-24T*	D 32	CM450DX-24S1	D	27	CM450DY-24S	D	11					
600	CM600DX-24T* CM600DXP-24T*	D D	28 39	CM600DY-24T*	D 32	CM600DX-24S1 CM600DXL-24S	D D	27 6	CM600DY-24S	D	11				CM600DY-24A CM600HA-24A CM600DU-24NF CM600DU-24NFH	D H D D 11 16 12 15
800									CM800DY-24S	D	12					
900												CM900DUC-24S	D	17		
1000	CM1000DX-24T* CM1000DXP-24T*	D D	29 40			CM1000DXL-24S	D	06								
1400									CM1400HA-24S*	H	36	CM1400DUC-24S	D	17		
Connection		H		D		T		R		M		E		E3		

\*1: A-Series have model names ending with A, NF-Series have model name ending with NF/NFH

★: Under Development ★: New Product

## Matrix of IGBT Modules 1700V

RoHS directive (2011/65/EU) compliant

V <sub>CES</sub> (V)	1700V																		
	Series I <sub>c</sub>	T-Series			T-Series			S/S1-Series			S/S1-Series			S/S1-Series			A-Series		
		NX Type	Connection	No.	std Type	Connection	No.	NX Type	Connection	No.	std Type	Connection	No.	MPD Type	Connection	No.	std Type	Connection	No.
35																			
50																			
75					CM75DY-34T**	D 30	CM75Mxa-34SA CM75Rx-34SA	M R 23 19						CM75DY-34A	D 08				
100	CM100TX-34T** CM100TXP-34T**	T T 33 37	CM100DY-34T**	D 30										CM100DY-34A	D 08				
150	CM150TX-34T** CM150TXP-34T**	T T 33 37	CM150DY-34T**	D 31	CM150DX-34SA CM150RXL-34SA	D R 20 21								CM150DY-34A	D 10				
200				CM200DY-34T**	D 31	CM200DX-34SA CM200EXS-34SA	D E 20 24							CM200DY-34A	D 10				
225	CM225DX-34T** CM225DXP-34T**	D D 28 39																	
300	CM300DX-34T** CM300DXP-34T**	D D 28 39	CM300DY-34T**	D 32	CM300DX-34SA	D 20								CM300DY-34A	D 11				
400				CM400DY-34T**	D 32										CM400DY-34A	D 18			
450	CM450DX-34T** CM450DXP-34T**	D D 28 39				CM450DXL-34SA	D 22												
500															CM500HA-34A	H 16			
600	CM600DX-34T** CM600DXP-34T**	D D 28 39				CM600DXL-34SA	D 22	CM600HA-34S*	H 36										
800									CM800HA-34S*	H 36									
900																			
1000									CM1000HA-34S*	H 36	CM1000DUC-34SA	D 17							
1400																			
Connection	H		D		T		R		M		E								

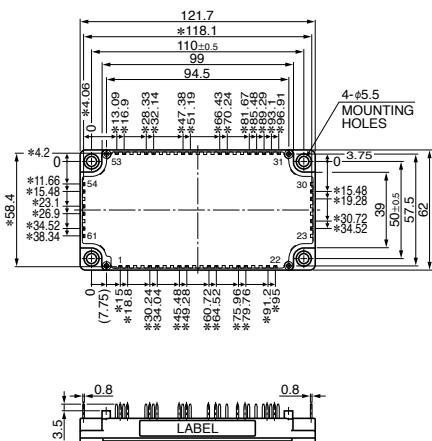
★★: Under Development ★: New Product

# Line-up of IGBT Modules

## Outline Drawing of IGBT Modules

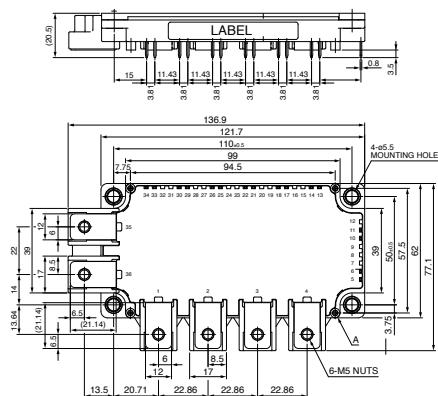
Unit:mm

**01** CM75,100MX-12A



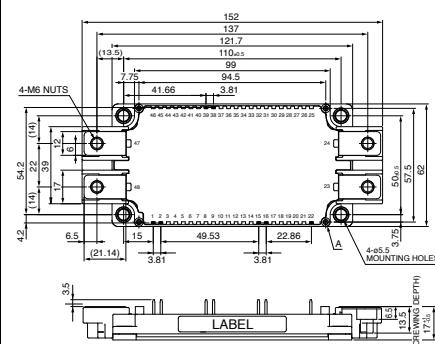
\*All dimensions with a tolerance of  $\pm 0.5$

**02** CM100,150,200RX-12A  
CM75RX-24S



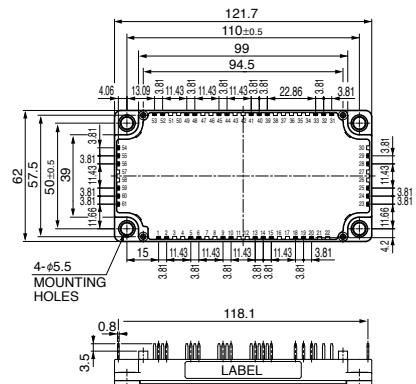
\*All dimensions with a tolerance of  $\pm 0.5$

**03** CM300,400DX-12A  
CM150,200DX-24S

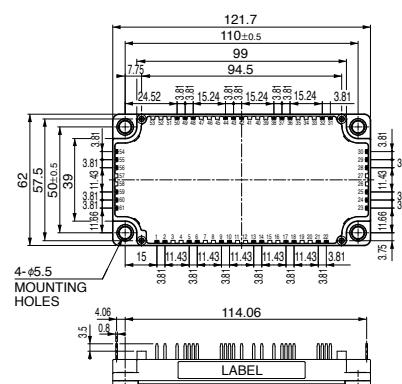


\*All dimensions with a tolerance of  $\pm 0.5$

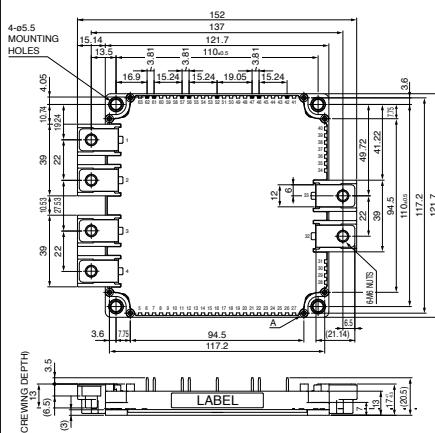
**04** CM35,50,75,100Mxa-24S



**05** CM75TX-24S

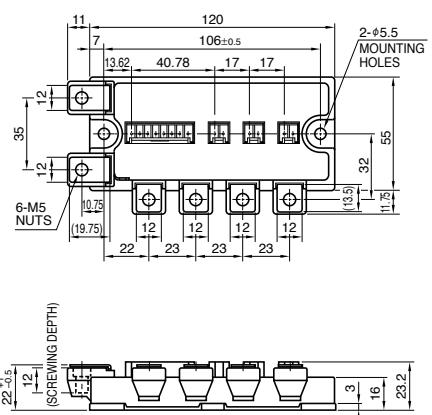


**06** CM600,1000DXL-24S

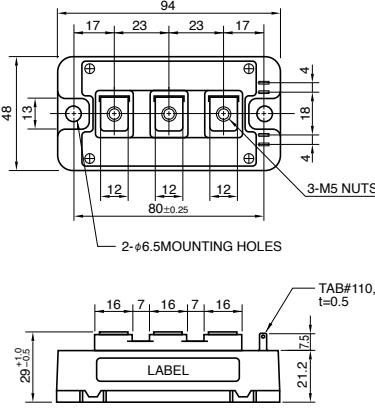


\*All dimensions with a tolerance of  $\pm 0.5$

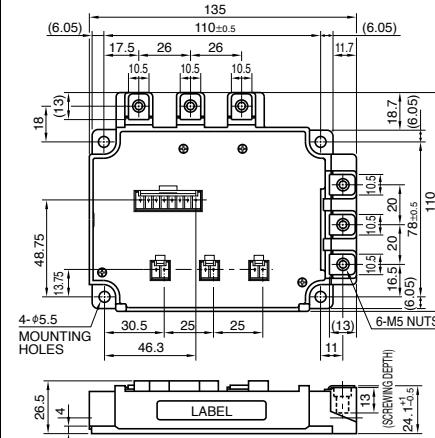
**07** CM75,100,150TL/RL-12NF  
CM50,75,100TL/RL-24NF



**08** CM150,200,300DY-12NF  
CM100,150DY-24NF  
CM100,150,200DY-24A  
CM75,100DY-34A  
CM100,150E3Y-24NF



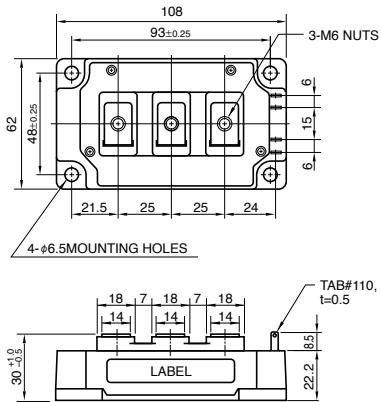
**09** CM200TL/RL-12NF  
CM150,200TL/RL-24NF



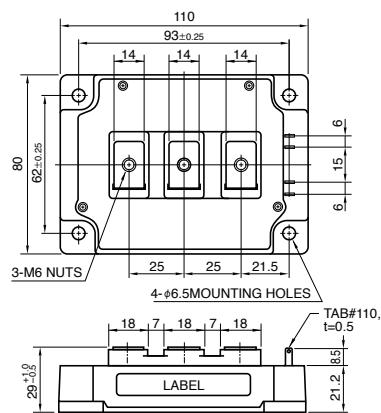
■ Outline Drawing of IGBT Modules

Unit:mm

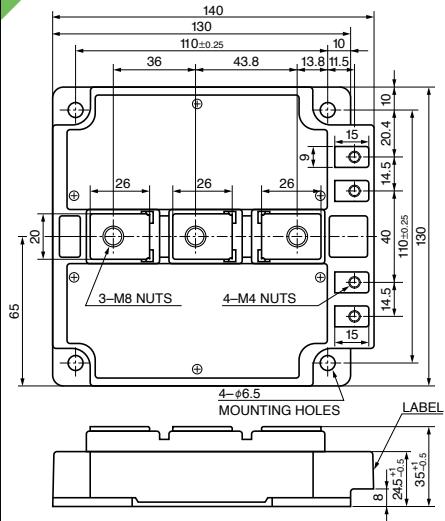
**10** CM400DY-12NF  
CM200DY-24NF  
CM300DY-24A  
CM300DY-24S  
CM150,200DY-34A



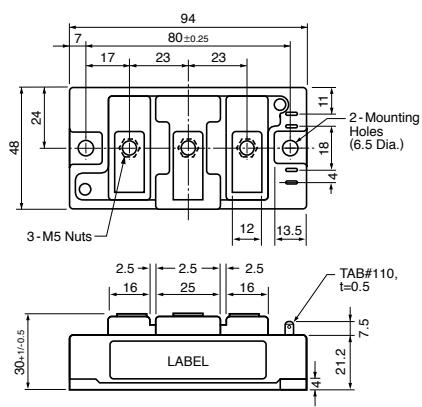
**11** CM600DY-12NF  
CM400DY-24NF  
CM400,600DY-24A  
CM300DY-34A  
CM400C1Y-24S  
CM450DY-24S  
CM600DY-24S  
CM300DY-24NF



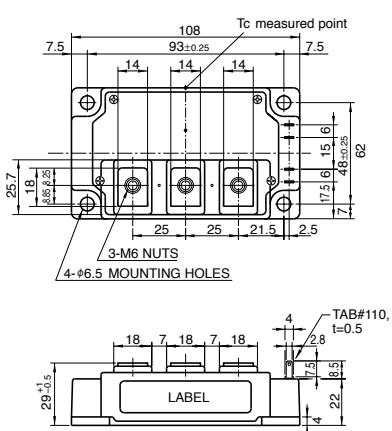
**12** CM600DU-24NF  
CM800DY-24S



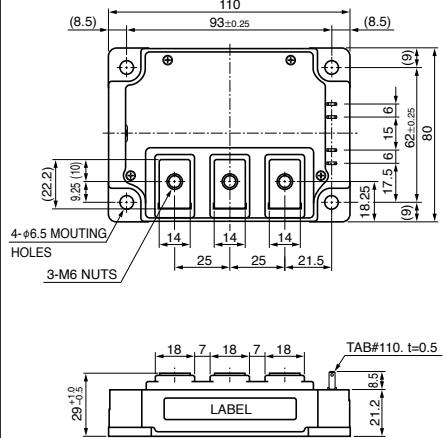
**13** CM100,150DUS-12F  
CM200DU-12NFH  
CM100,150DU-24NFH



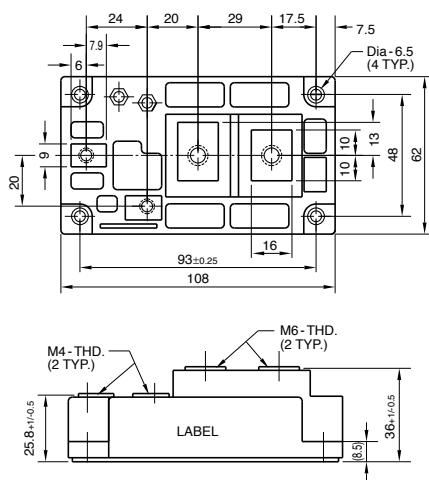
**14** CM300,400DU-12NFH  
CM200,300DU-24NFH



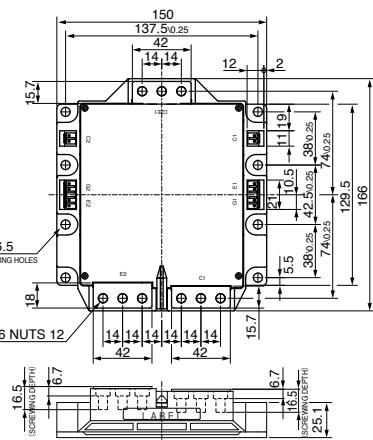
**15** CM600DU-12NFH  
CM400,600DU-24NFH



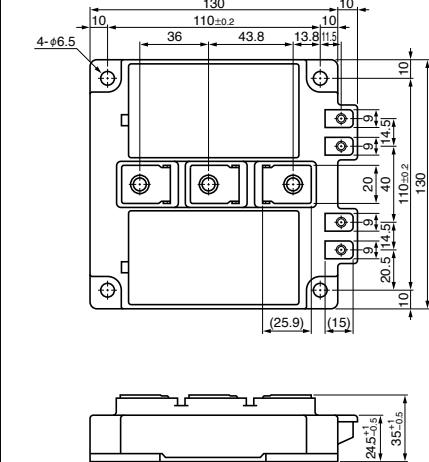
**16** CM400,600HA-24A  
CM500HA-34A



**17** CM900,1400DUC-24S  
CM1000DUC-34SA



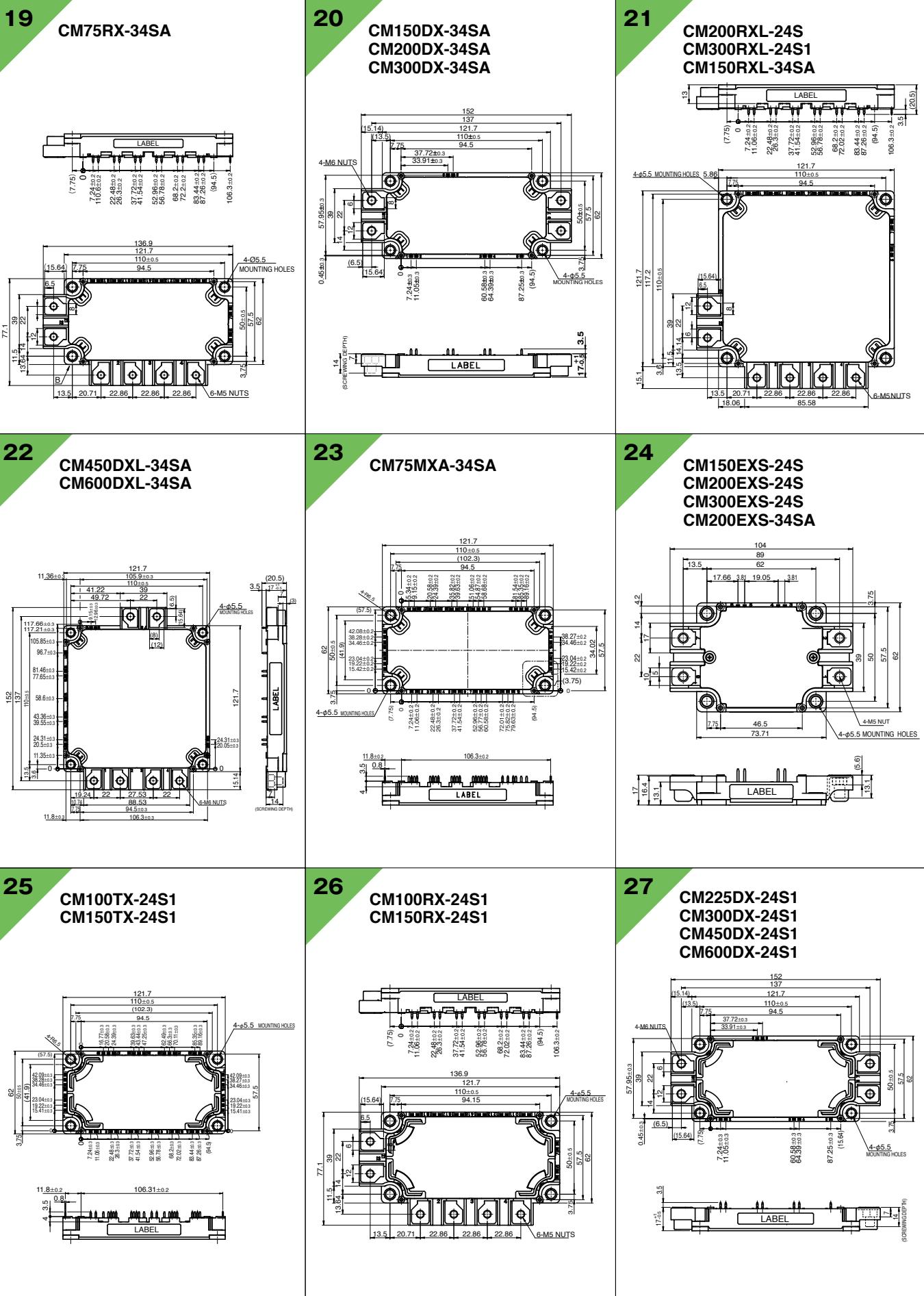
**18** CM400DY-34A



# Line-up of IGBT Modules

## Outline Drawing of IGBT Modules

Unit:mm

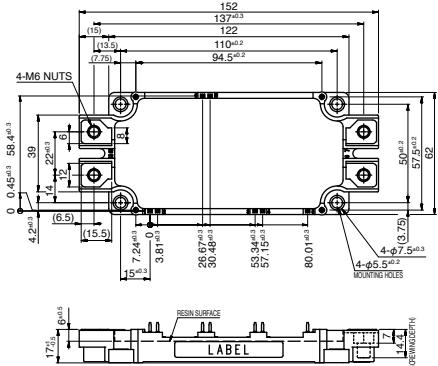


■ Outline Drawing of IGBT Modules

Unit:mm

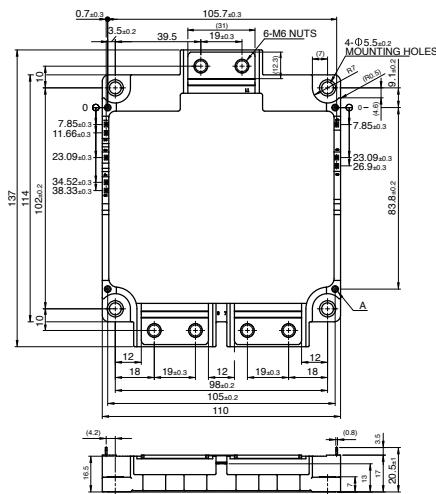
**28**

**CM300,450,600DX-13T  
CM225,300,450,600DX-24T**



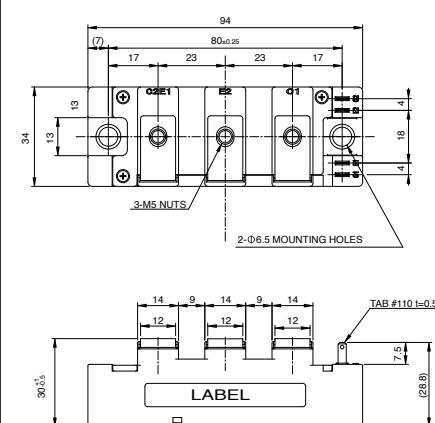
**29**

**CM1000DX-24T**



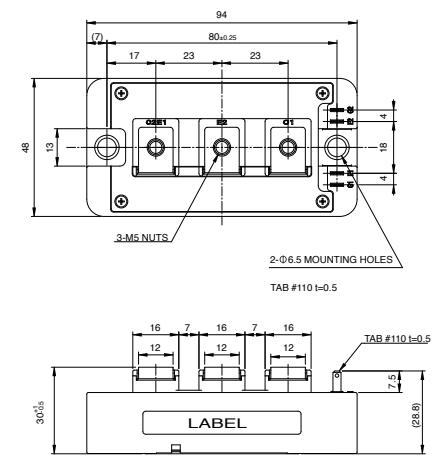
**30**

**CM100,150,200DY-13T  
CM100,150DY-24T**



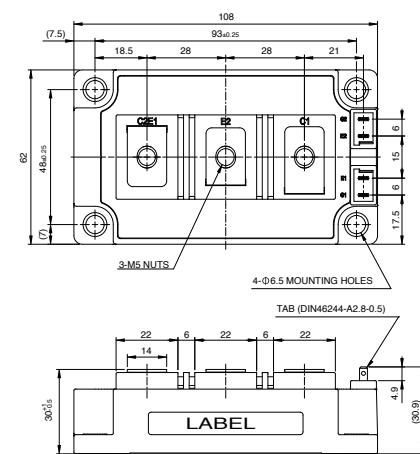
**31**

**CM300,400DY-13T  
CM200,300DY-24T**



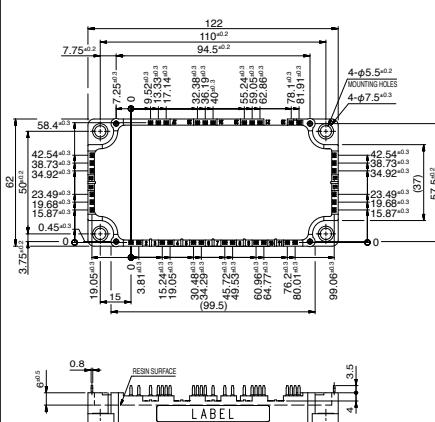
**32**

**CM600DY-13T  
CM450,600DY-24T  
CM450,600C1Y-24T**



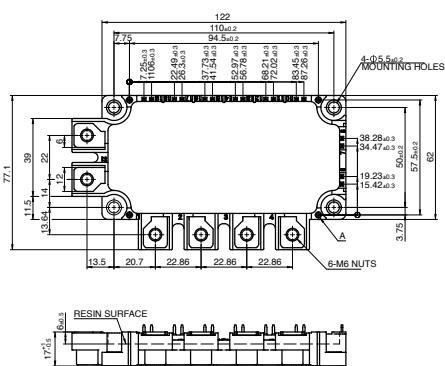
**33**

**CM100,150,200TX-13T  
CM100,150,200TX-24T  
CM100,150TX-34T**



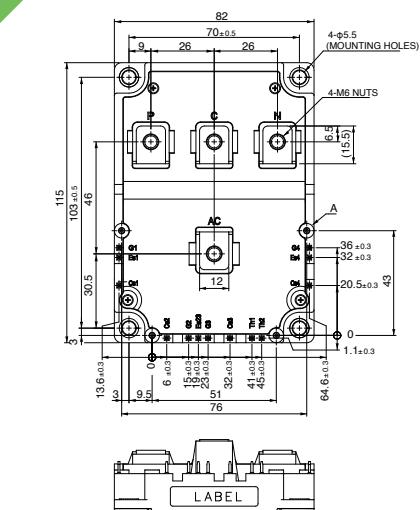
**34**

**CM150,200RX-13T  
CM100,150RX-24T**



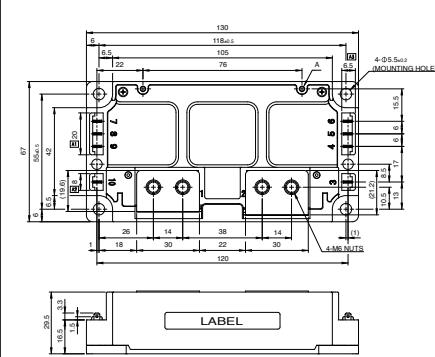
**35**

**CM400ST-24S1**



**36**

**CM500C2Y-24S  
CM1400HA-24S  
CM1000HA-34S  
RM1400HA-24S**



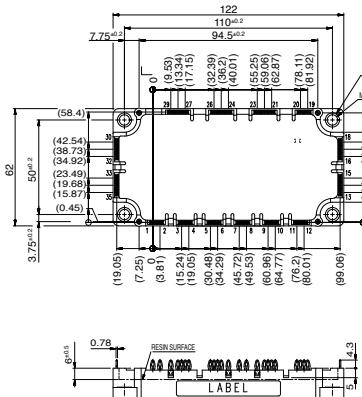
# Line-up of IGBT Modules

## Outline Drawing of IGBT Modules

Unit:mm

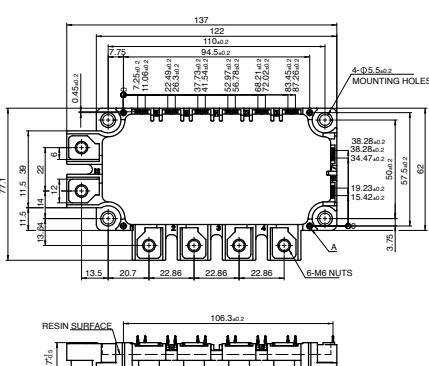
**37**

CM100,150,200TXP-13T  
CM100,150,200TXP-24T  
CM100,150TXP-34T



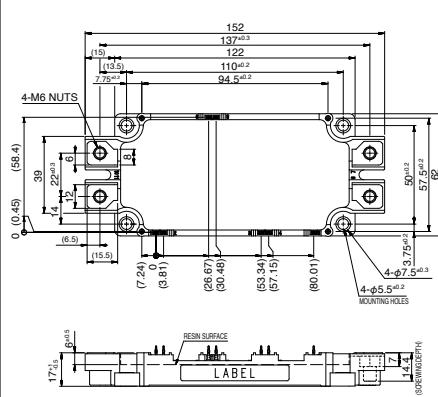
**38**

CM150,200RXP-13T  
CM100,150RXP-24T



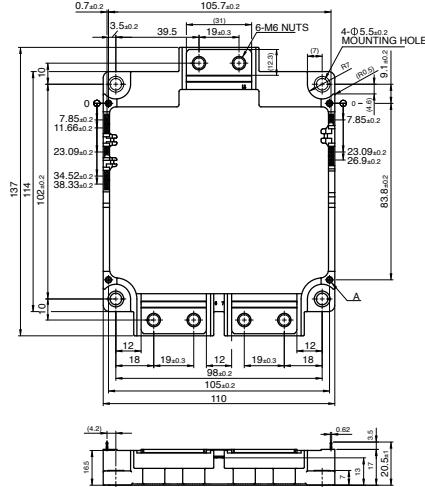
**39**

CM300,450,600DXP-13T  
CM225,300,450,600DXP-24T



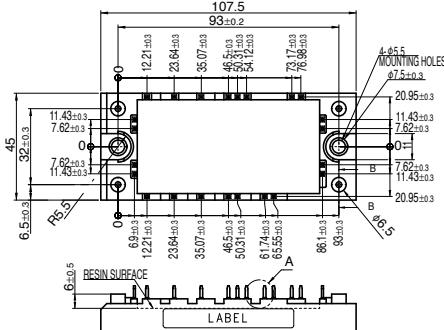
**40**

CM1000DXP-24T



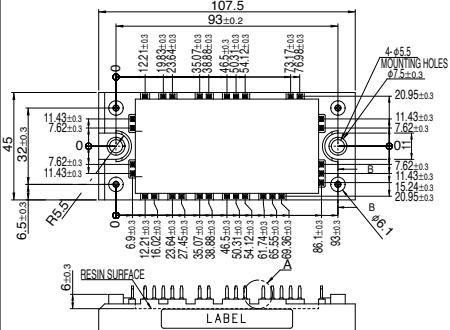
**41**

CM35,50MXUA-24T/24T1



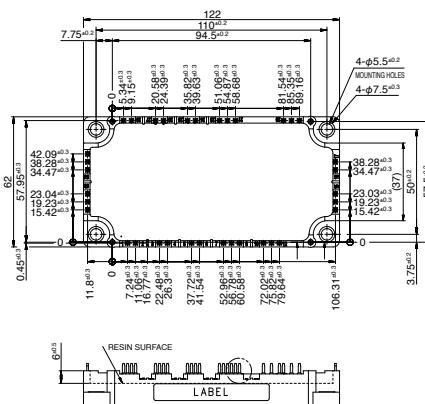
**42**

CM50,75,100MXUB-13T/13T1  
CM75MXUB-24T/24T1



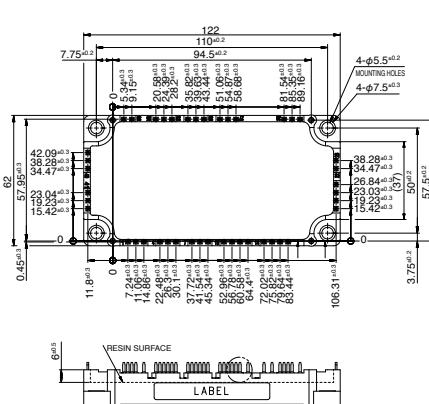
**43**

CM75,100MXUC-24T/24T1



**44**

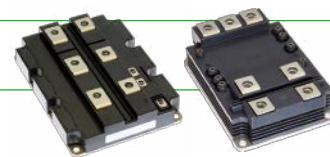
CM100/150MXUD-13T/T1  
CM150MXUD-24T/24T1



# HVIGBT Modules



## New Products



### X Series HVIGBT Modules

**Existing compatible package: Standard type**  
**Contributes to smaller, higher-capacity inverter systems by expanding lineup**

	std. Type	
1.7kV	2400A/3600A	1600A/2400A
3.3kV	1200A/1800A	1200A
4.5kV	900A/1350A/1500A	900A/1000A
6.5kV	600A/900A/1000A	600A

#### <Main Features>

- Power loss reduced by incorporating 7th-generation IGBT and RFC<sup>1</sup> diode
- Industry-leading power<sup>2</sup> for increased inverter capacity
- External size reduced 33% while maintaining the same voltage resistance and rated current as conventional products,<sup>3</sup> contributing to inverter downsizing
- Optimal package internal structure realizes improved heat dissipation, humidity resistance and flame retardance, increasing product life

<sup>1</sup>\*1 RFC : Relaxed field of cathode

<sup>2</sup>\*2 3.3kV - 6.5kV (as of Apr. 5, 2018 based on Mitsubishi Electric research)

<sup>3</sup>\*3 Comparison of X Series CM1200HC-66X and H Series CM1200HC-66H

**New common frame package: LV100/HV100 type**  
**Class-leading current density contributes to increased power output in inverter systems**

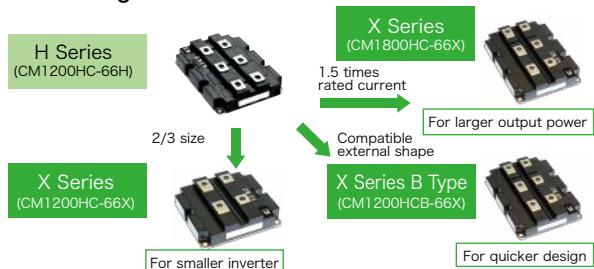
	LV100 Type	HV100 Type
1.7kV	1000A/1200A	
3.3kV	450A/600A	450A/600A
6.5kV		225A/300A

#### <Main Features>

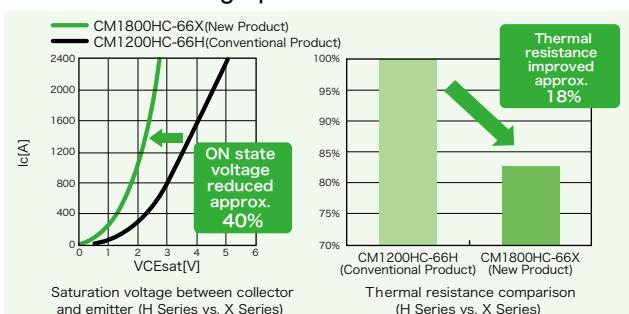
- Power loss reduced by incorporating 7th-generation IGBT and RFC<sup>1</sup> diode
- Industry's highest 3.3kV/600A Si module power density of 8.57A/cm<sup>2</sup><sup>4</sup> contributes to increased power output and efficiency
- Terminal layout optimized for easy paralleling and flexible inverter configurations and capacities
- New package structure offers extra reliability

<sup>4</sup>\*4 As of Apr. 5, 2018, based on Mitsubishi Electric research

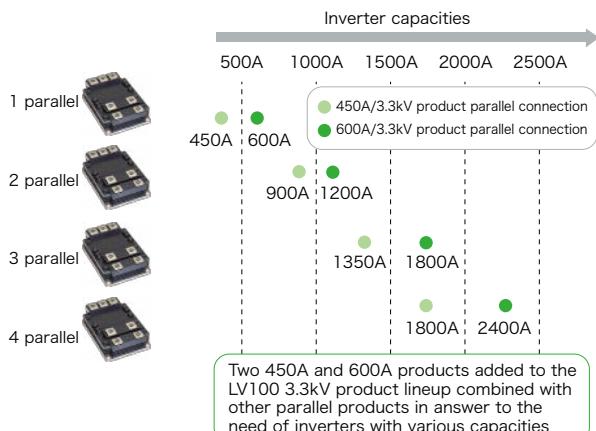
### Positioning from conventional series



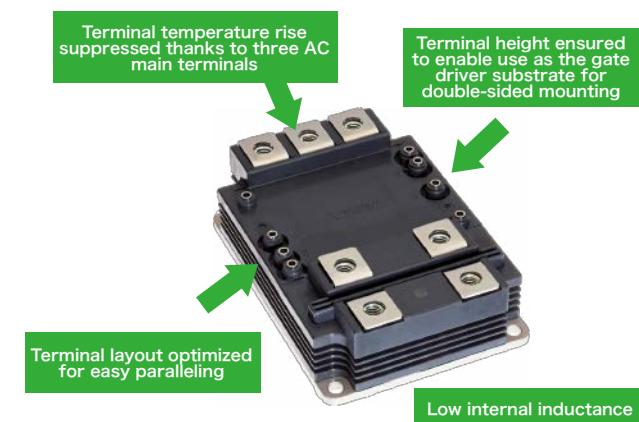
### Characteristics graph



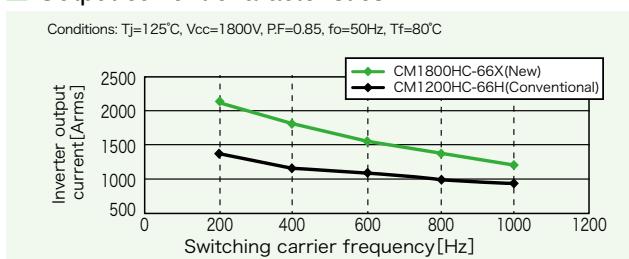
### Various current ratings for optimal system design



### Package features (LV100 type)



### Output current characteristics



## Line-up of HVIGBT Modules

■ Series Matrix of HVIGBT/HVIPM (No.: Number of outline drawing, see page 26 and 28)

[Type] A: Al base plate / 6 kViso B:Cu base plate C:AlSiC base plate / 6 kViso D:AlSiC base plate / 10kViso E:Al base plate / 10kViso

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★★: Under Development

\*There are possibility to change the type of auxiliary terminals.

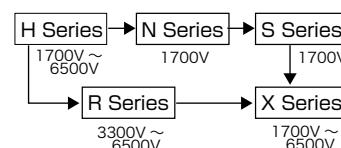
■ Series Matrix of HVDIODE Modules (No.: Number of outline drawing, see page 28)

[Type] B:Cu base plate, C:AlSiC base plate / 6 kViso, D:AlSiC base plate / 10kViso

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★★: Under Development

## ■ Evolution of HVIGBT Module Series



## Type Name Definition of IGBT Modules

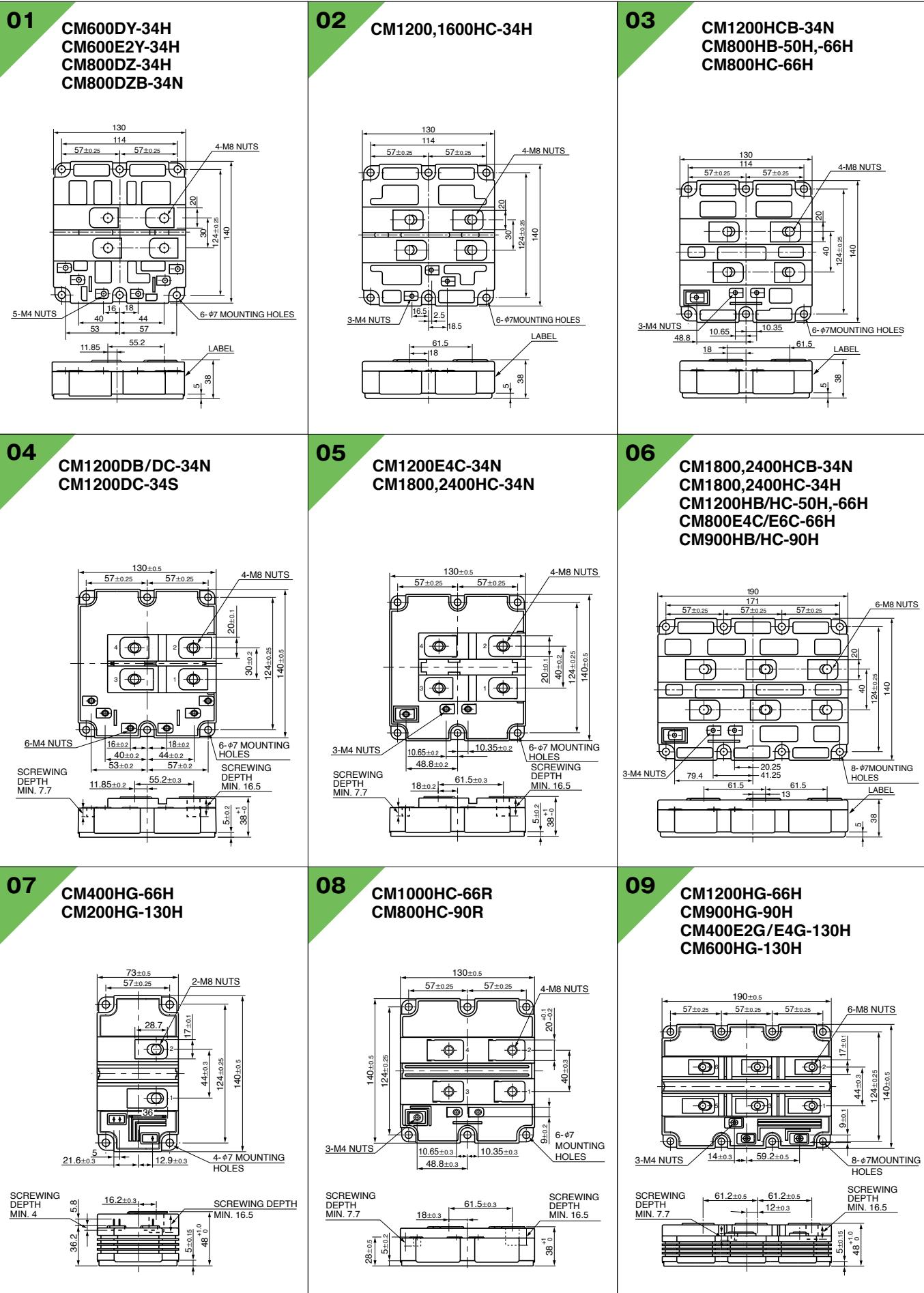
The diagram illustrates the breakdown of the marking scheme:

- CM**: Rating current class
- 1800**: Connection type
- H**: Outline drawing and package type
- C**: Voltage class
- 66**: Series name
- X**:

CM: IGBT, RM: DIODE, PM: HVIPM

■ Outline Drawing of HVIGBT Modules

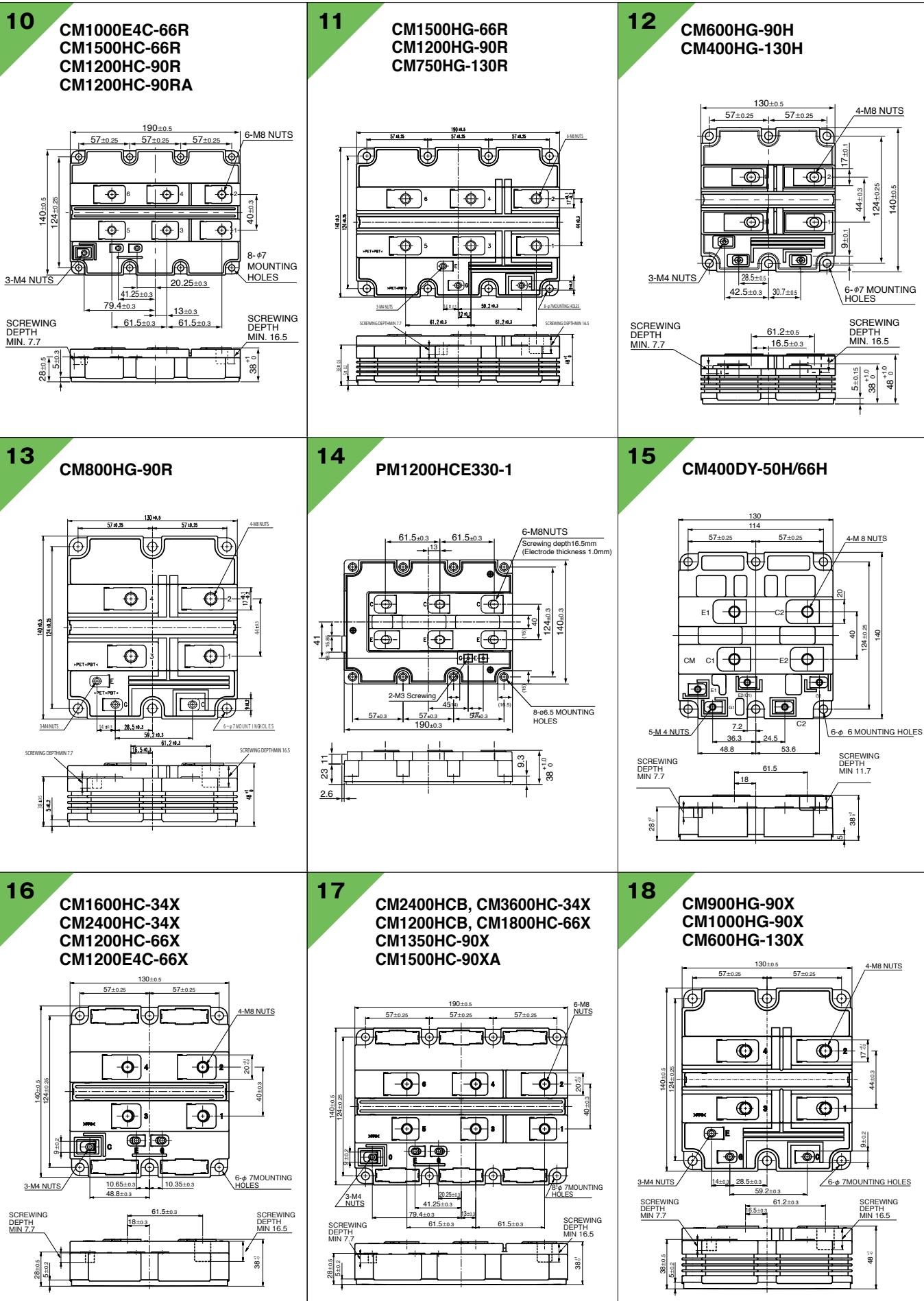
Unit:mm



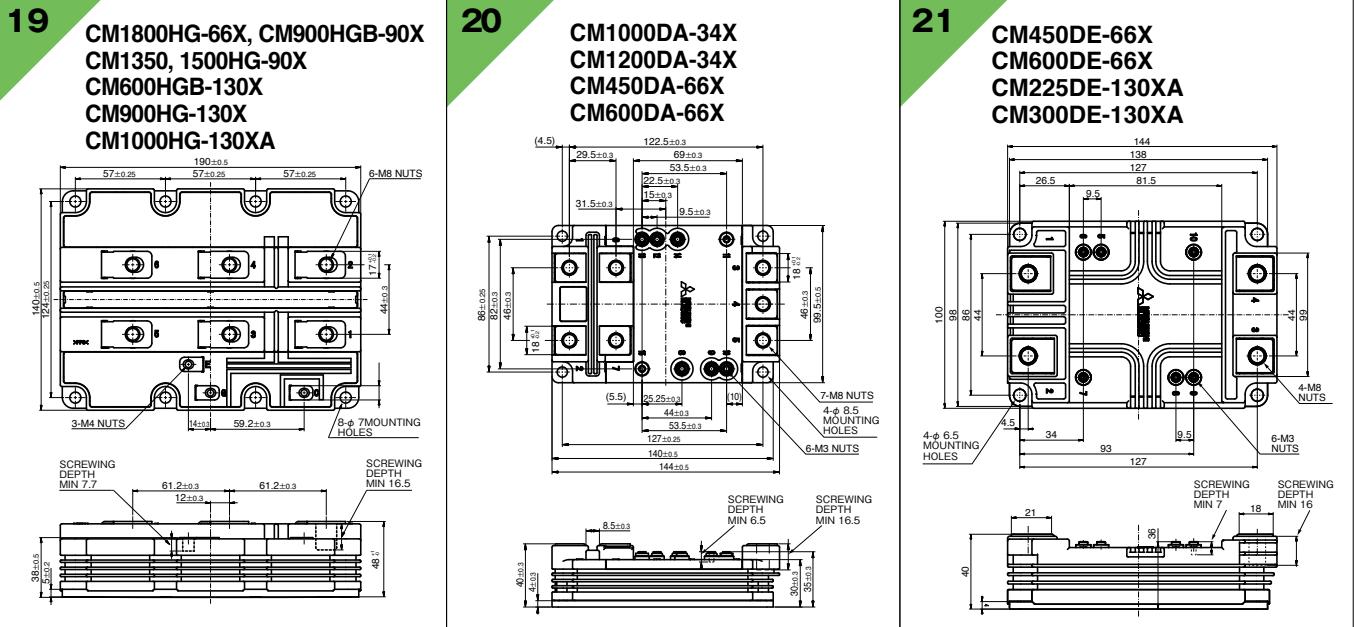
# Line-up of HVIGBT Modules

## Outline Drawing of HVIGBT Modules

Unit:mm

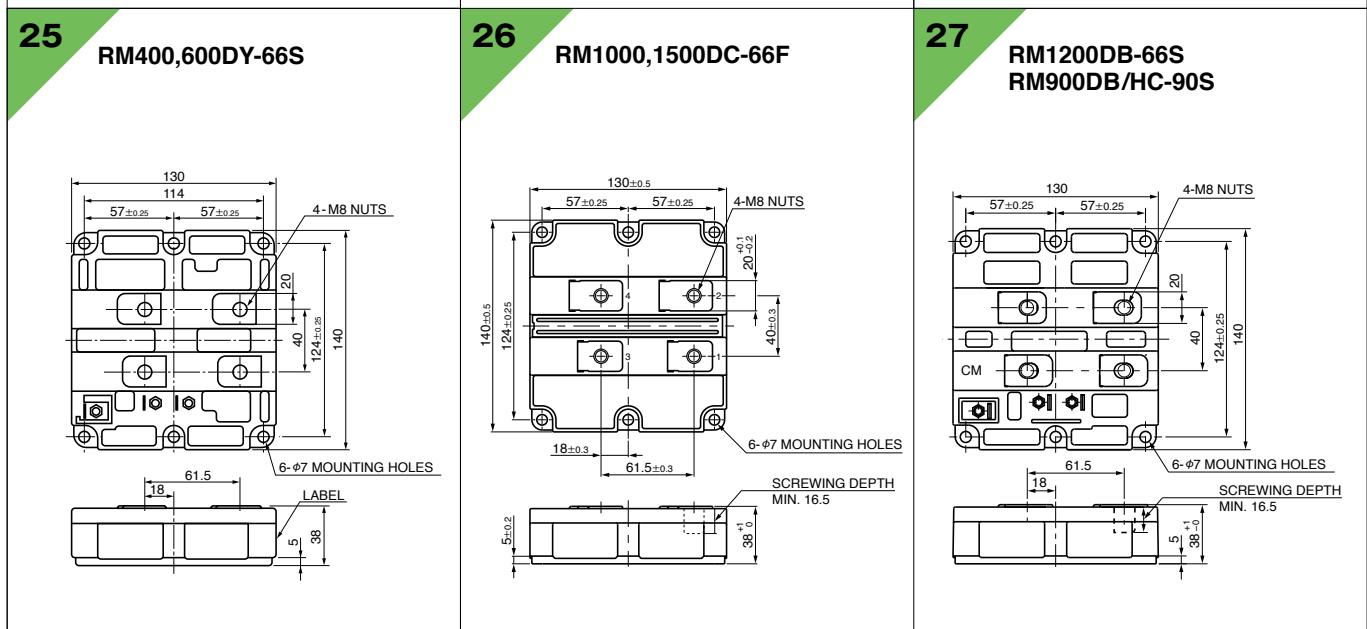
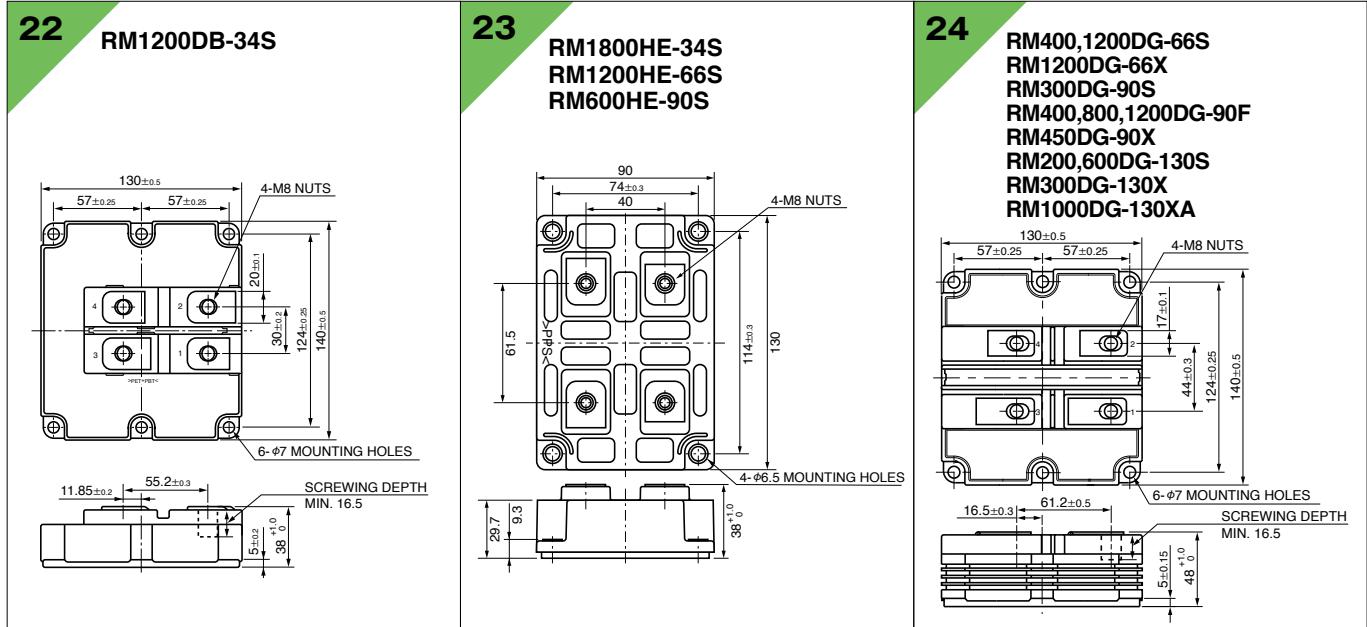


\*There are possibility to change the type of auxiliary terminals.



Unit:mm

## Outline Drawing of HVDIODE Modules



# Power Modules for Electric and Hybrid Vehicles



## New Products

Package with 6-in-1 connection and integrated water-cooled fin contributes to more compact, high-power inverters for EVs/HEVs



### High Power J1 Series Power Modules for EVs/HEVs

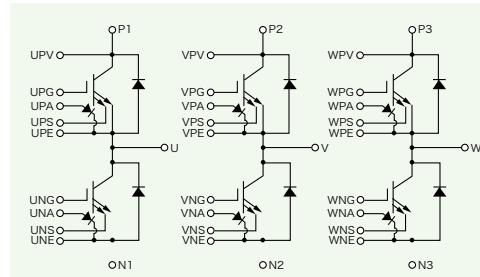
CT1000CJ1B060,  
CT600CJ1B120

#### <Main Features>

- Integrated direct water-cooling structure with cooling fins and 6-in-1 connection contribute to more compact inverters for EVs/HEVs
- Direct lead bonding (DLB) structure ensures high reliability
- Loss further reduced by incorporating 7th-generation IGBT built with a CSTBT™\* structure
- Completely lead-free, conforms to RoHS directives (2011/65/EU)
- Suitable for a variety of electric and hybrid vehicle inverters

\*CSTBT™: Mitsubishi Electric's unique IGBT that utilizes the carrier cumulative effect.

### Block Diagram



## Features

### Common

- Long power/temperature cycle life
- High-precision on-chip temperature sensor
- High traceability in managing materials/components for each product throughout the entire production process

- Package structure compliant with the End-of-Life-Vehicles Directive, regulations relating to substances of environmental concern

### J Series T-PM (Transfer-molded Power Module)

- Structure incorporates transfer molding and original direct lead bonding(DLB) technique
- DLB structure reduces internal wiring resistance and inductance
- Completely Pb-free (including the pins)

### J1 Series (6-in-1)

- Cooling fin integrated direct water-cooled structure and 6-in-1 configuration contribute to minimize the automobile inverter
- DLB structure realizes high reliability
- Installation of the 7th generation IGBT adapting the CSTBT™\* structure realizes a further reduction in loss
- On-chip current sensor that enables high-speed current-cutoff protection is installed

### Matrix of 650V Power Modules (No. : Number of outline drawing, please refer to page 30)

V <sub>CES(V)</sub>	650V						
	Series	J1 Series		J Series			
I <sub>c(A)</sub>		Power Module with pin fin	Connection	No.	T-PM	Connection	
300		-	-	-	CT300DJG060**	D 02	
600		CT600CJ1A060	C 01		CT600DJH060**	D 03	
700		CT700CJ1A060*	C 01		-	-	
1000		CT1000CJ1B060*	C 04		-	-	
Connection		C			D		

★: New Product ★★: Under Development

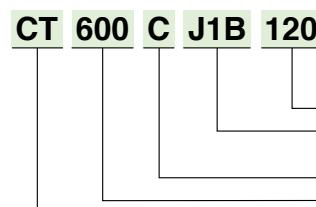
### Matrix of 1200V Power Modules

(No. : Number of Outline Drawing, please refer to page 30)

V <sub>CES(V)</sub>	1200V			
	Series	J1 Series		
I <sub>c(A)</sub>		Power Module with pin fin	Connection	
300		CT300CJ1A120**	C 01	
600		CT600CJ1B120*	C 04	
Connection		C		

★: New Product ★★: Under Development

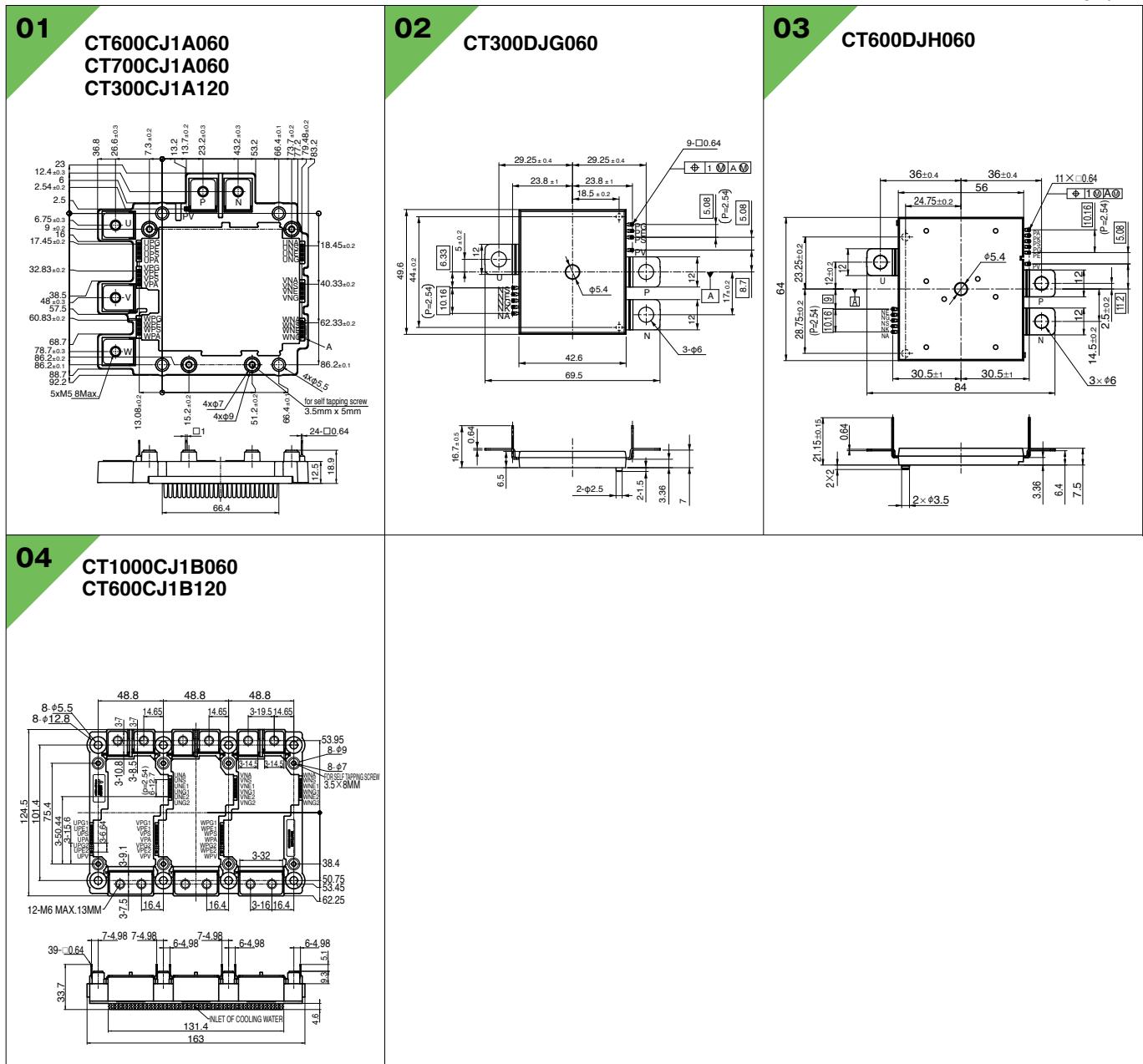
### Type Name Definition of Power Modules for Electric and Hybrid Vehicles



- Voltage class
- Series name and structure
- Connection type
- Rating current class
- CT: IGBT

## ■ Outline Drawing of Power Modules for Electric and Hybrid Vehicles

Unit:mm



# POWER MODULES

Please visit our website for further details.

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